

Reference Schematic For PX30 MINI

PX30_MINI_EVB_V1.0

PMIC: RK809-1 (5BUCK + 9LDO + Codec)
RAM: DDR3 /LPDDR3/DDR4
ROM: eMMC/Nand + TF card
Interface: MIPI CSI/MIPI DSI/UART/I2S/RMII

Index

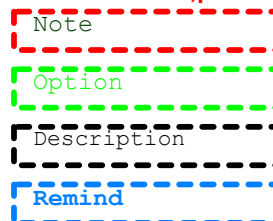
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- 04.I2C MAP
- 05.Power diagram and Sequence
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- 11.PX30 OSC/PMUIO
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Note

NOTE 1: Component parameter description

1. DNP stands for component not mounted temporarily
2. If Value or option is DNP, which means the area is reserved without being mounted
3. If Flash is compatible, please notice when eMMC is used, the option is that @eMMC is mounted, @Nand is not mounted when Nand is used, the option is that @Nand is mounted, @eMMC is not mounted

NOTE 2: Please use our recommended components to avoid too many changes.For more informations about the second source,please refer to our AVL.



Bill of Materials

Header:

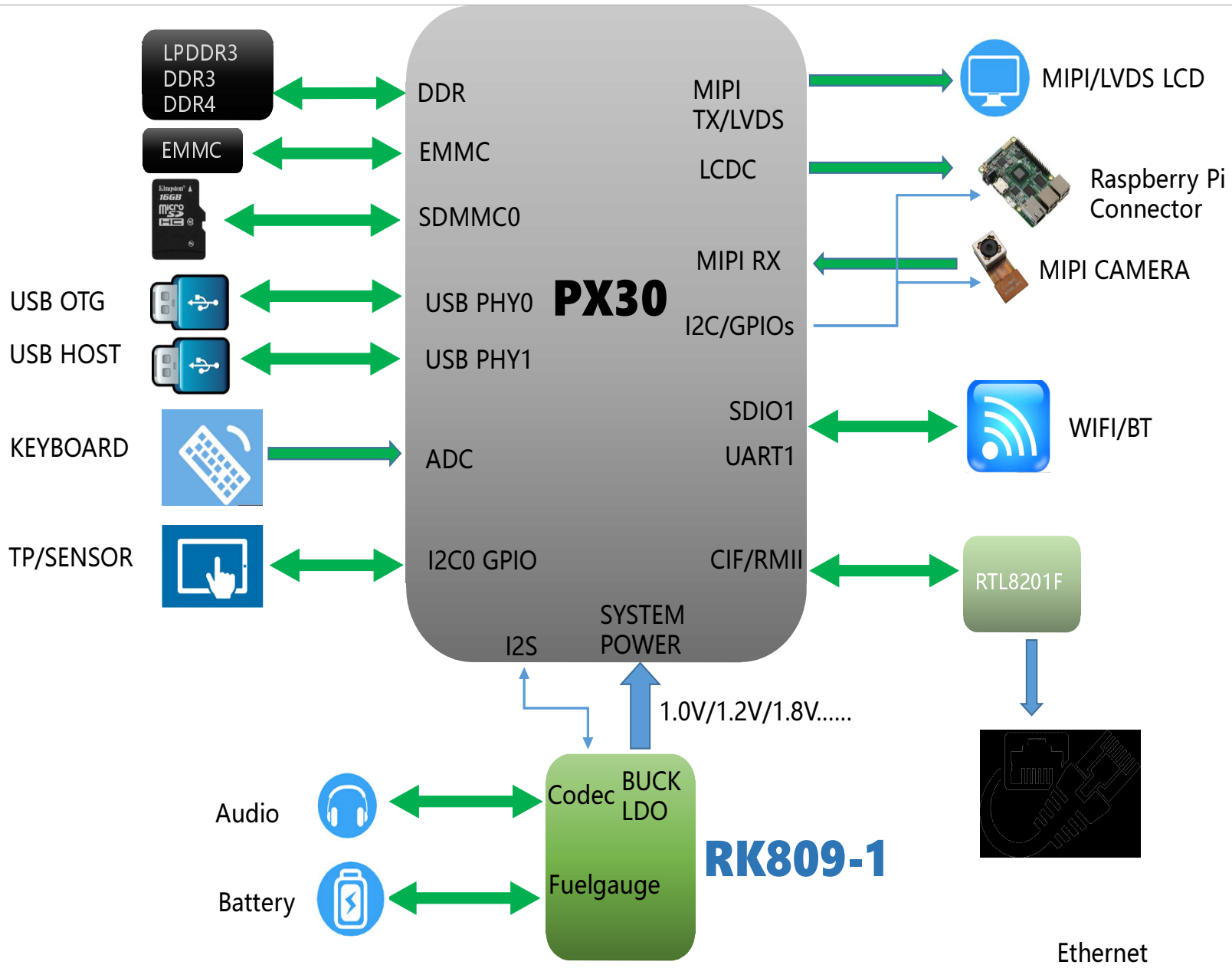
Item\tPart\tDescription\tPCB Footprint\tReference\tQuantity\tOption

Combined property string:

{Item}\t{Value}\t{Description}\t{PCB Footprint}\t{Reference}\t{Quantity}\t{Option}

 瑞芯微电子		Fuzhou Rockchip Electronics	
Project:	PX30 MINI EVB		
File:	01.Index		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	2 of 32


Version	Date	Author	Change List	Approved
V1.0	20180504	XHF	First edition for PX30	



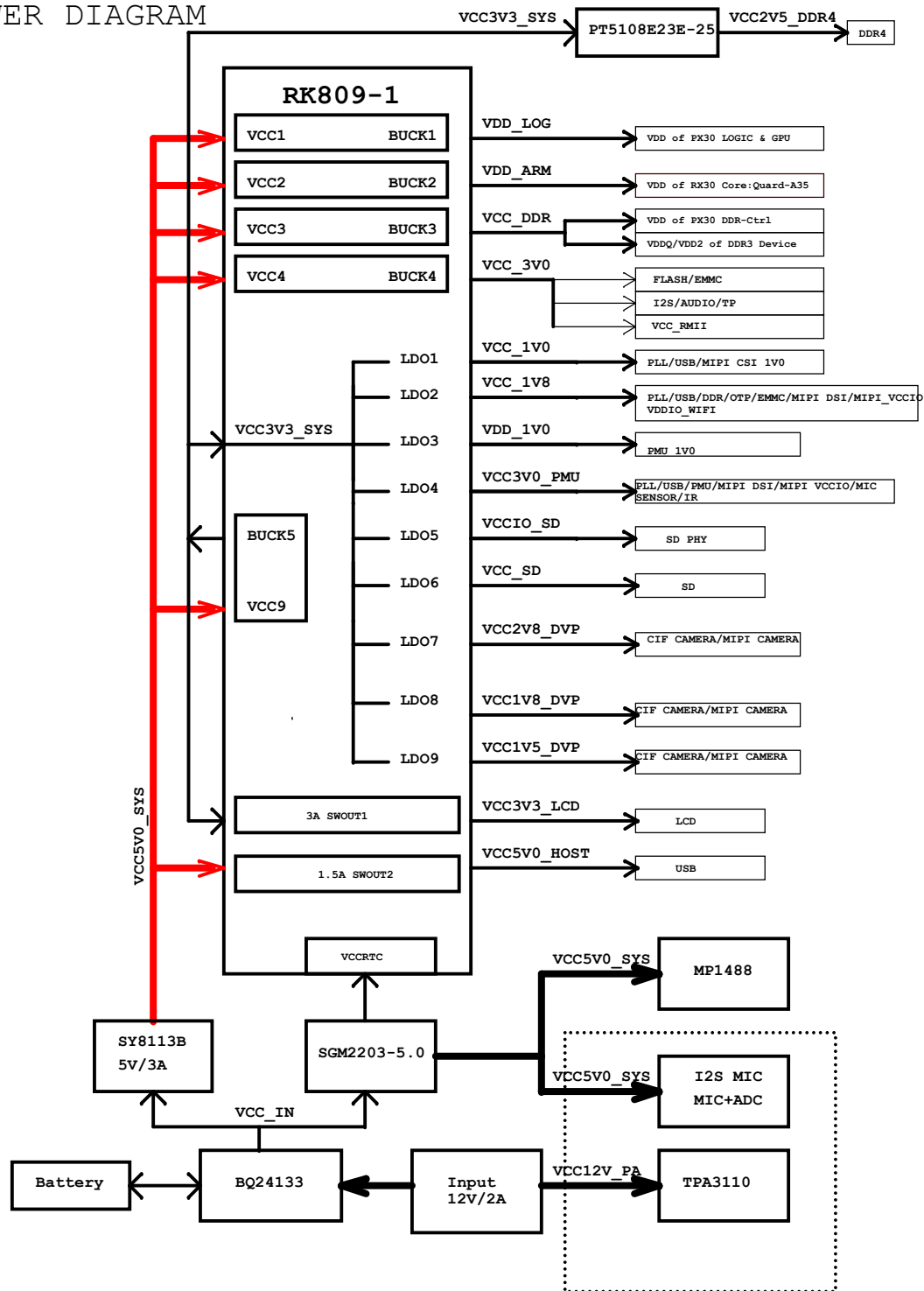
Rockchip 瑞芯微电子		Fuzhou Rockchip Electronics	
Project:	PX30 MINI EVB		
File:	03.Block Diagram		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	4 of 32

I2C MAP

Port	Pin name	Domain	Bus name	Pull-up voltage	Slave Device	Slave Addr (MS 7Bits)	Note	Slave Bus Capability
I2C0	I2C0_SCL/GPIO0_B0_u I2C0_SDA/GPIO0_B1_u	PMUIO2	I2C0_SCL_PMIC I2C0_SDA_PMIC	VCC3V0_PMU	Rockchip RK809	0x20	PMIC	
I2C1	I2C1_SCL/PMU_DEBUG5/GPIO0_C2_u I2C1_SDA/GPIO0_C3_u	PMUIO2	I2C1_SCL I2C1_SDA	VCC3V0_PMU	MMA8452Q	0x1d	Accelerometer	100kHz, 400kHz
					LIS3DH	0x19	Accelerometer	100kHz, 400kHz
					LSM303D	0x1d	Accelerometer+Magnetic	100kHz, 400kHz
I2C2	I2C2_SCL/GPIO2_B7_u I2C2_SDA/GPIO2_C0_u	VCCIO3	I2C2_SCL_CAM I2C2_SDA_CAM	VCC_RMII	OV5695	0X36	MIPI Camera	

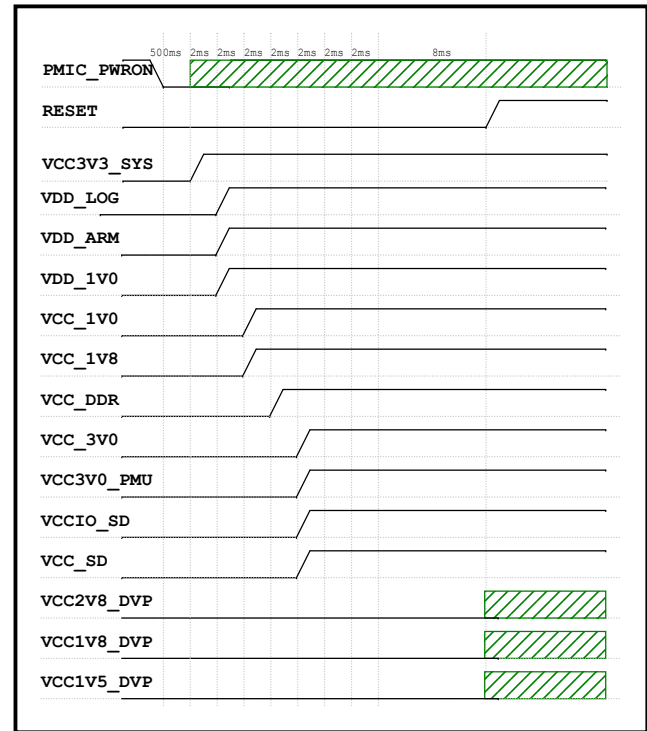
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Project:	PX30 MINI EVB		
File:	04.I2C MAP		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	5 of 32

POWER DIAGRAM

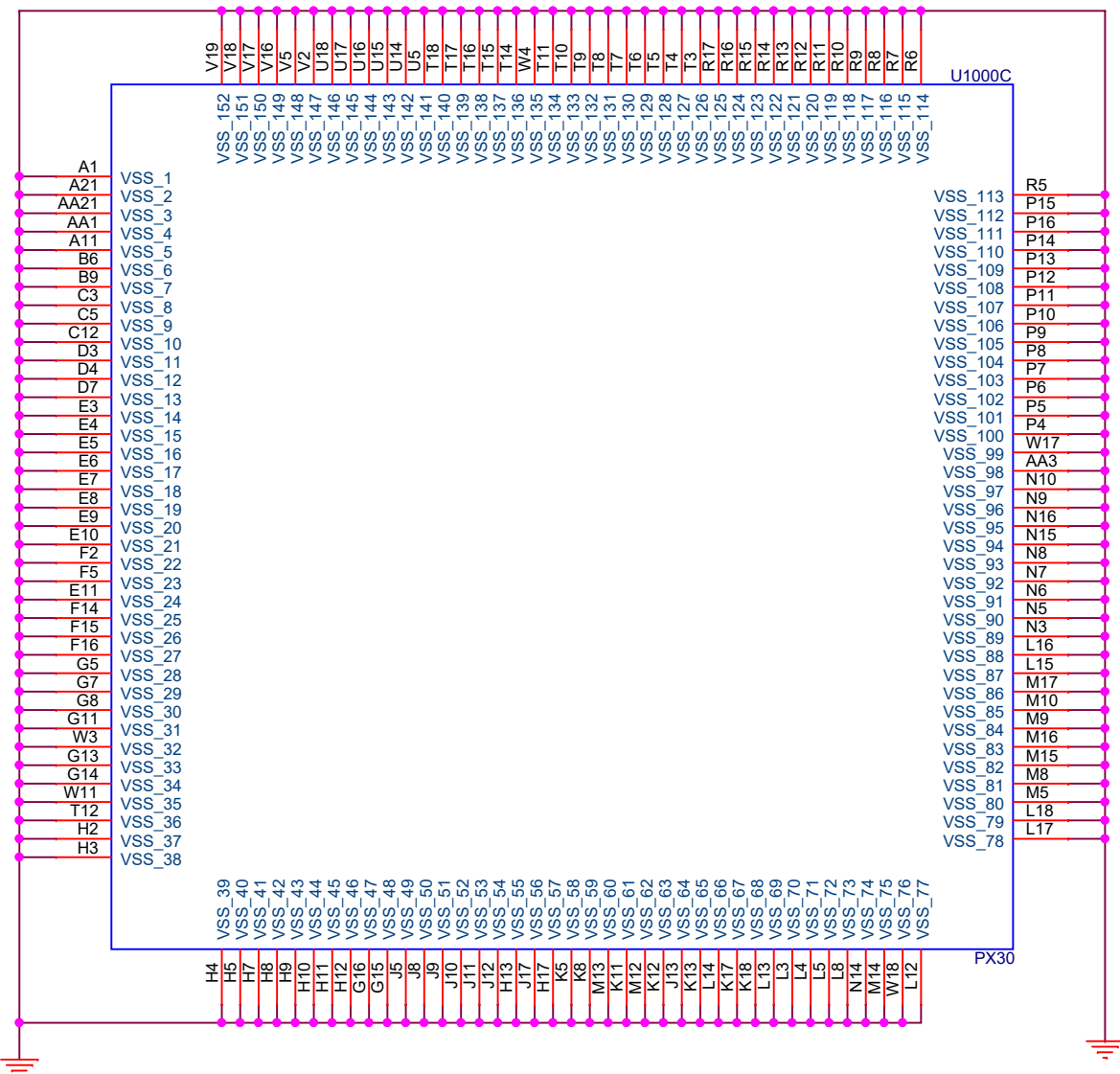


RK809-1 Power-on Sequence

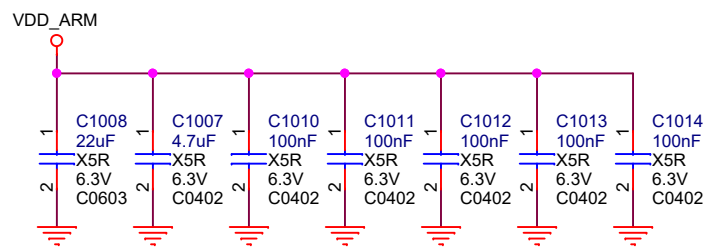
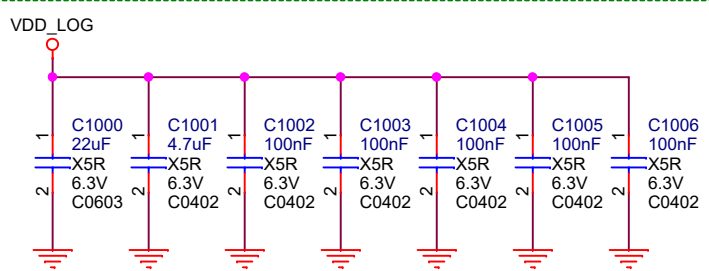
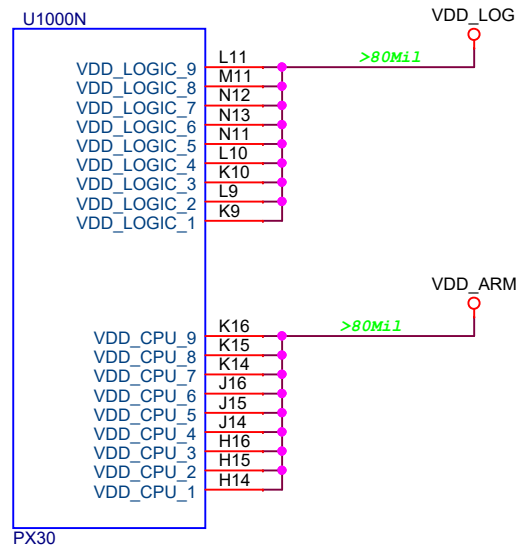
PowerName	PMIC Channel	Time Slot (step 2mS)	Default voltage	Supply Limit	Default ON/OFF	Sleep ON/OFF	Peak Current
VDD_ARM	BUCK1	Slot:2	1.0V	2.5A	ON	OFF	1160mA
VDD_LOG	BUCK2	Slot:2	1.0V	2.5A	ON	OFF	1020mA
VCC_DDR	BUCK3	Slot:4	1.5A	FB=0.6V	ON	ON	790mA
VCC_3V0	BUCK4	Slot:5	3.0V	1.5A	ON	ON	360mA
VCC3V3_SYS	BUCK5	Slot:1	3.3V	1.5A	ON	ON	
VCC1V0	LDO1	Slot:3	2.5V	500mA	ON	ON	
VCC1V8	LDO2	Slot:3	1.8V	500mA	ON	ON	236mA
VDD1V0	LDO3	Slot:2	1.0V	500mA	ON	ON	13.6mA
VCC3V0_PMU	LDO4	Slot:5	3.0V	100mA	ON	ON	9mA
VCCIO_SD	LDO5	Slot:5	3.0V	500mA	ON	ON	
VCC_SD	LDO6	Slot:5	3.0V	500mA	ON	ON	
VCC2V8_DVP	LDO7	Slot:5	2.8V	500mA	OFF	OFF	
VCC1V8_DVP	LDO8	Slot:5	1.8V	500mA	OFF	OFF	
VCC1V5_DVP	LDO9	Slot:5	1.5V	500mA	OFF	OFF	
RESET	RESETB	Slot:11	OD				




Part C GND



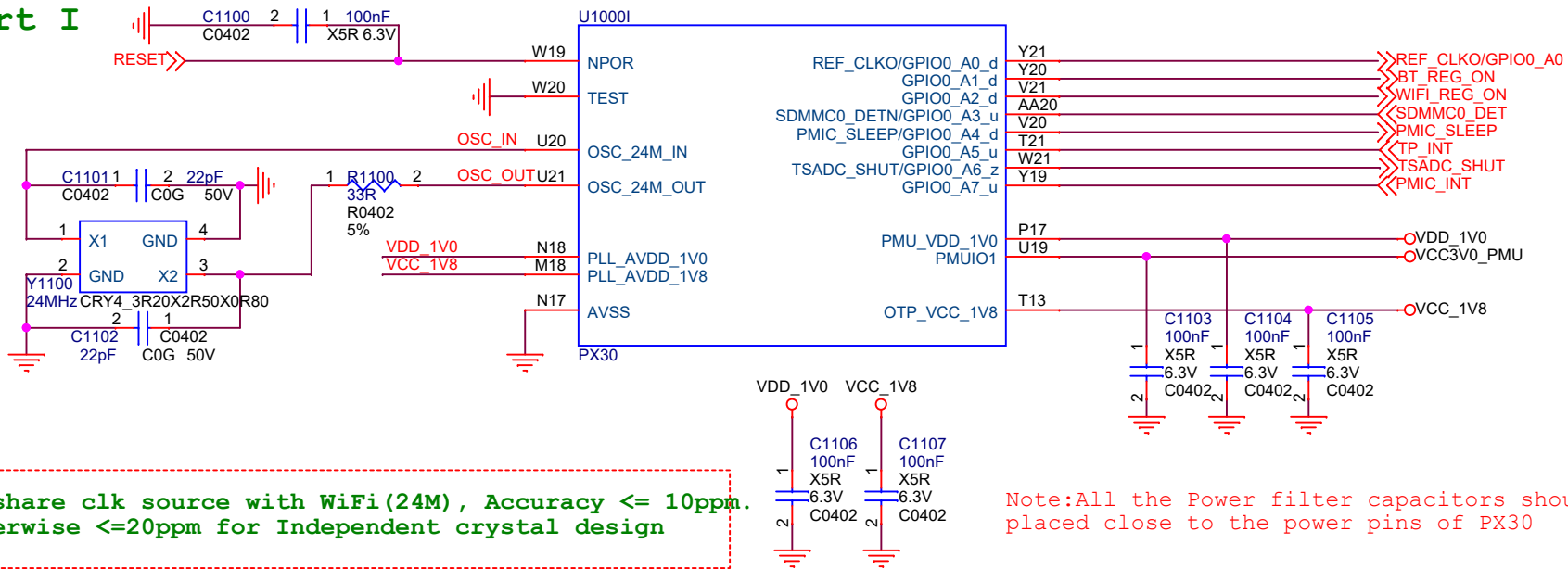
Part N Power



Place these decoupling capacitances close to the SOC power supply balls

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Project:	PX30 MINI EVB
File:	10.PX30 Power
Date:	Monday, May 28, 2018
Designed by:	XIAOHF
Rev:	V1.0
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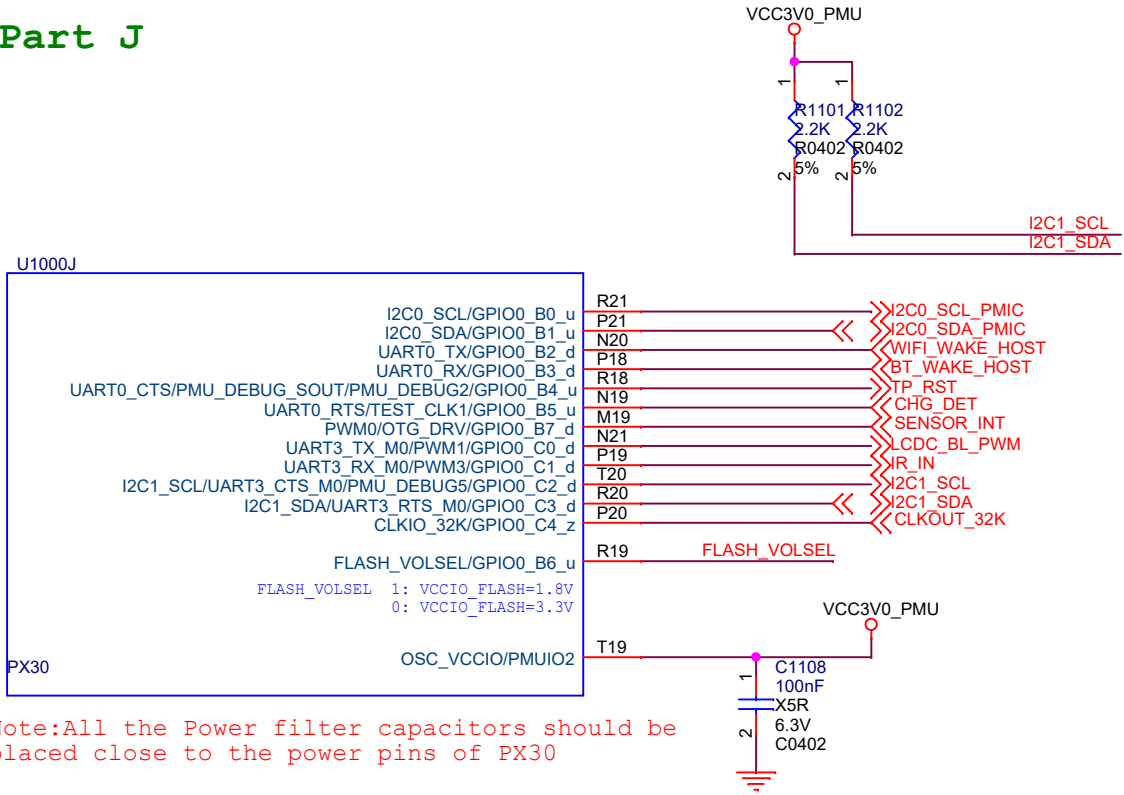
Part I



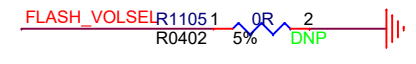
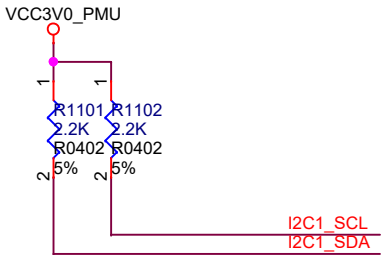
If share clk source with WiFi(24M), Accuracy <= 10ppm.
 Otherwise <=20ppm for Independent crystal design

Note:All the Power filter capacitors should be placed close to the power pins of PX30

Part J



Note:All the Power filter capacitors should be placed close to the power pins of PX30

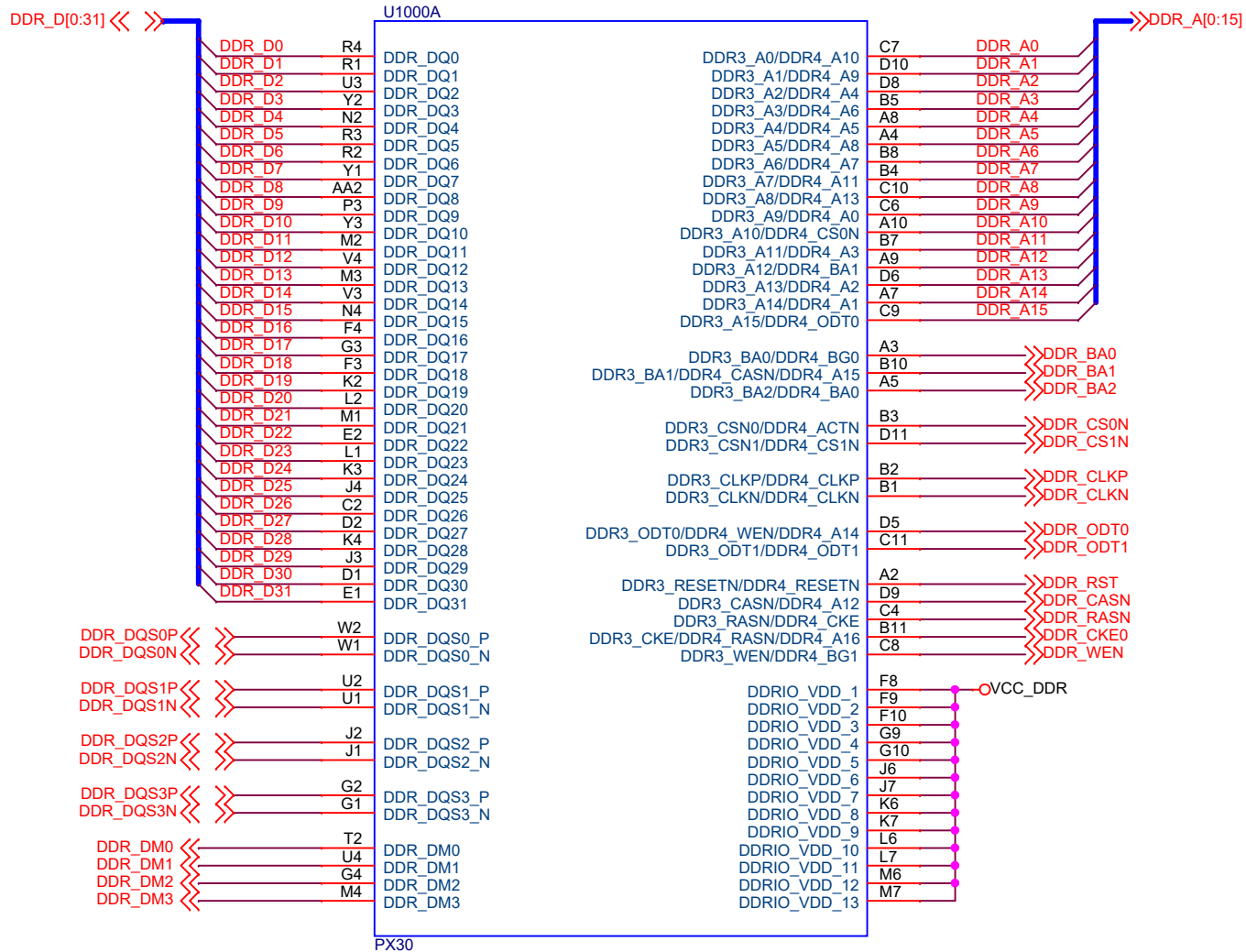


Floating or Pull-up FLASH_VOLSEL=1	Pull-down FLASH_VOLSEL=0
VCCIO_FLASH=1.8V	VCCIO_FLASH=3.3V

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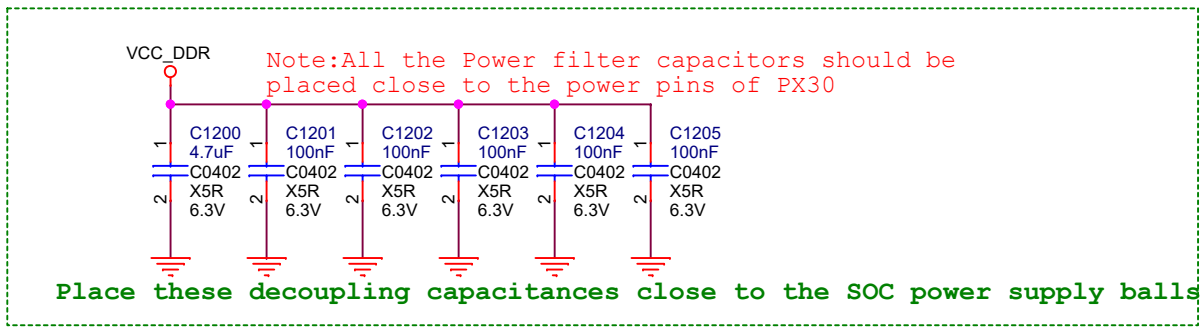
Project:	PX30 MINI EVB		
File:	11.PX30 OSC/PMUIO		
Date:	Monday, May 28, 2018	Rev:	V1.0
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Part A DDR Controller



DDR3/DDR4 PIN MUX

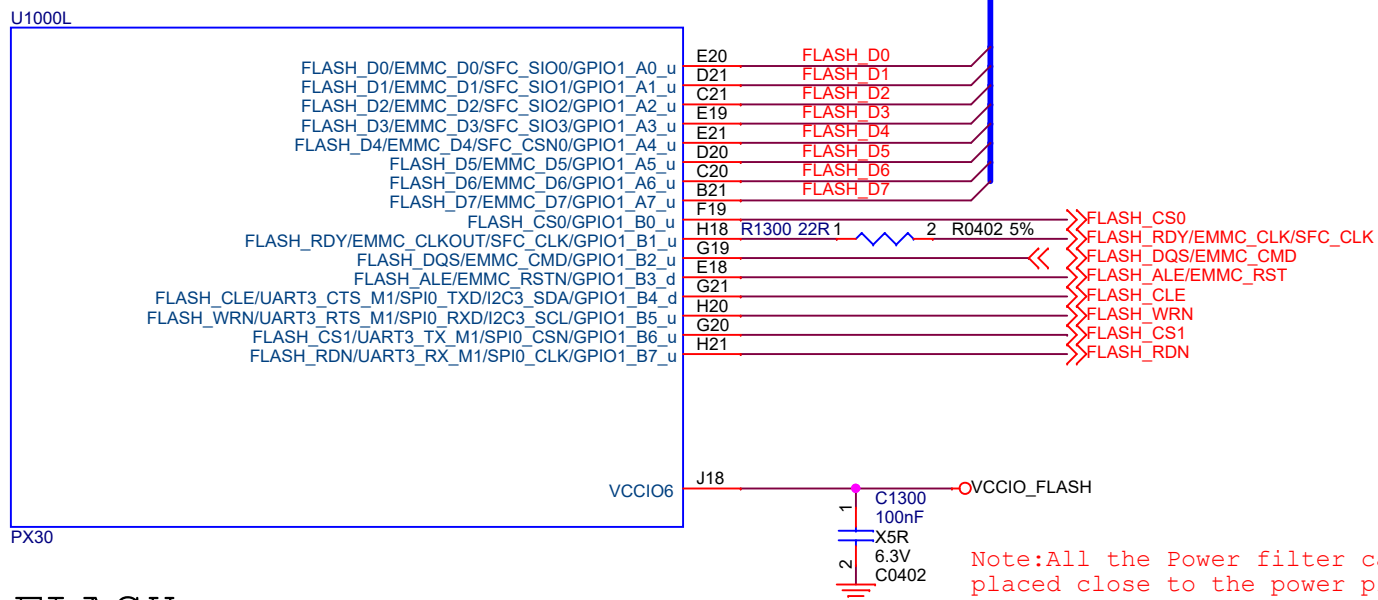
DDR3_A0	DDR4_A10
DDR3_A1	DDR4_A9
DDR3_A2	DDR4_A4
DDR3_A3	DDR4_A6
DDR3_A4	DDR4_A5
DDR3_A5	DDR4_A8
DDR3_A6	DDR4_A7
DDR3_A7	DDR4_A11
DDR3_A8	DDR4_A13
DDR3_A9	DDR4_A0
DDR3_A10	DDR4_CS0n
DDR3_A11	DDR4_A3
DDR3_A12	DDR4_BA1
DDR3_A13	DDR4_A2
DDR3_A14	DDR4_A1
DDR3_A15	DDR4_ODT0
DDR3_BA0	DDR4_BG0
DDR3_BA1	DDR4_CASn/DDR4_A15
DDR3_BA2	DDR4_BA0
DDR3_CS0N	DDR4_ACTn
DDR3_CS1N	DDR4_CS1n
DDR3_ODT0	DDR4_WEn/DDR4_A14
DDR3_ODT1	DDR4_ODT1
DDR3_CLKP	DDR4_CLKP
DDR3_CLKn	DDR4_CLKn
DDR3_CKE	DDR4_RASn/DDR4_A16
DDR3_RASn	DDR4_CKE
DDR3_CASn	DDR4_A12
DDR3_WEn	DDR4_BG1
DDR3_RST	DDR4_RST



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Project:	PX30 MINI EVB		
File:	12.PX30 DDR Controller		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	9 of 32

Part I

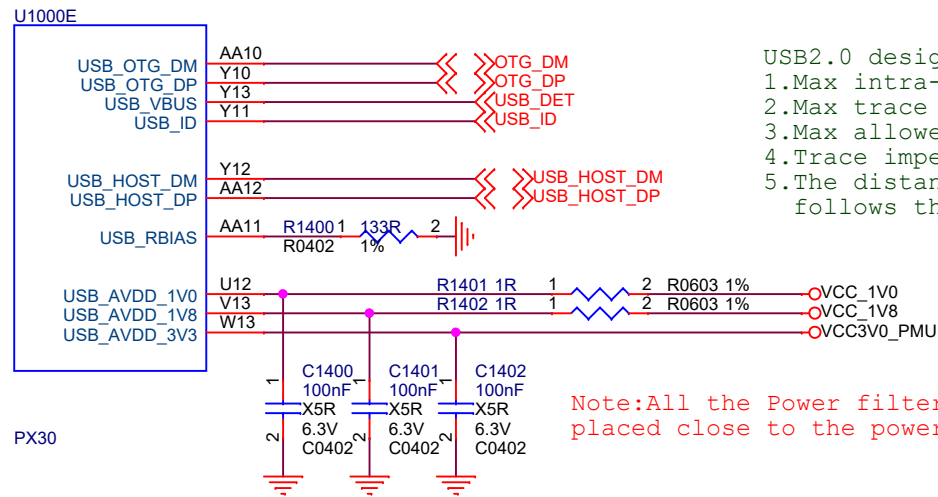


FLASH

Note: All the Power filter capacitors should be placed close to the power pins of PX30

 Fuzhou Rockchip Electronics 瑞芯微电子	
Project:	PX30 MINI EVB
File:	13.PX30 Flash Controller
Date:	Monday, May 28, 2018
Designed by:	XIAOHF
Rev:	V1.0
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Part E

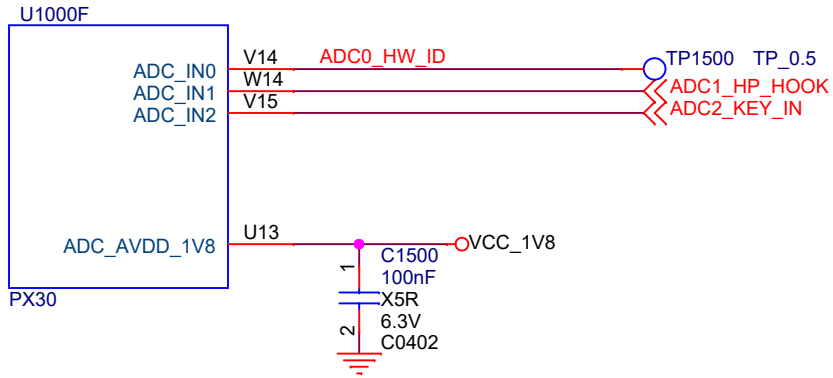


USB2.0 design rules:

1. Max intra-pair skew < 4ps;
2. Max trace length < 6inches;
3. Max allowed via < 6;
4. Trace impedance 90ohm+/-10%;
5. The distance between other signals follows the 3W rule;

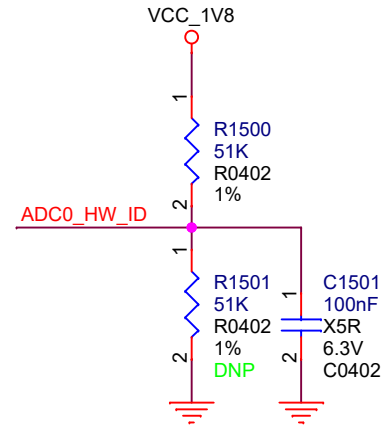
Note: All the Power filter capacitors should be placed close to the power pins of PX30

Part F



Note: All the Power filter capacitors should be placed close to the power pins of PX30

It is reserved for the hardware version of the product.
If it is not needed, it can be removed.



HW ID

ADC0_HW_ID	Pull-up Resistance	Pull-down Resistance	ADC Value
Version0 (Default)	51K	DNP	1024

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Project: PX30 MINI EVB

File: 15.PX30 ADC

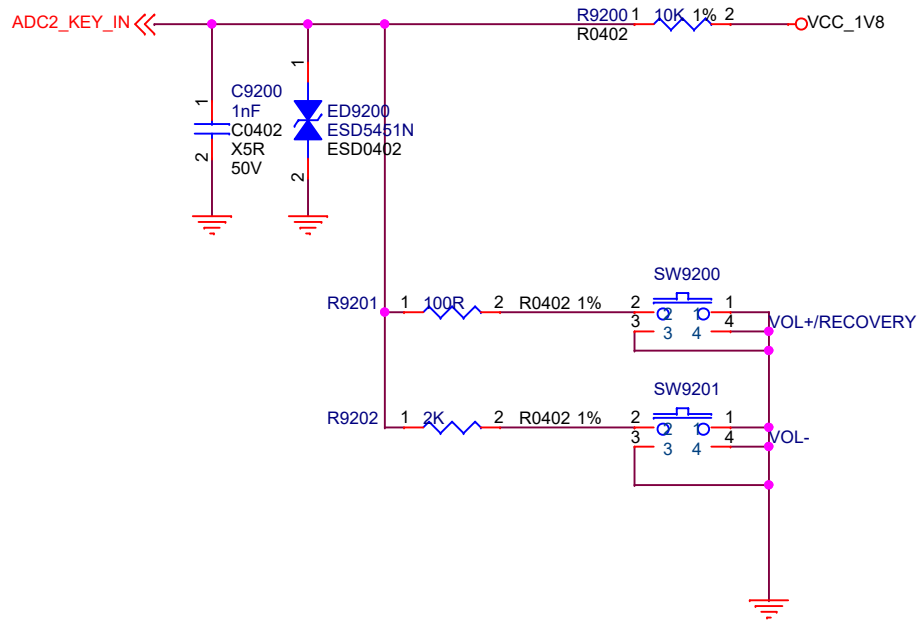
Date: Monday, May 28, 2018

Rev: V1.0

Designed by: XIAOHF

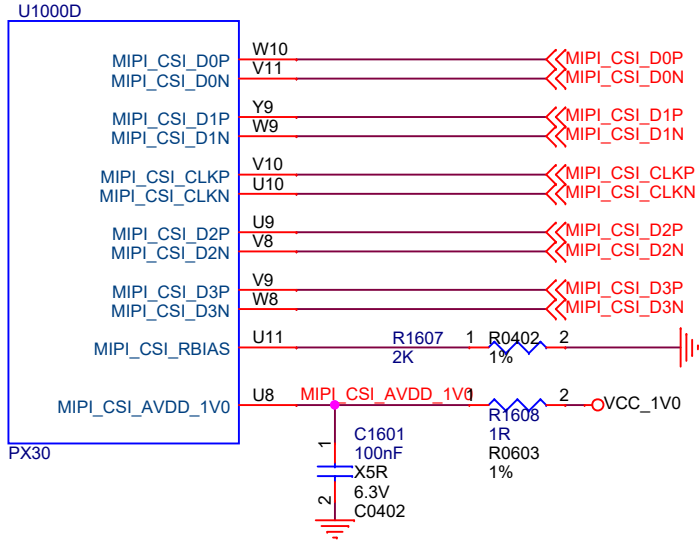
Sheet: 12 of 32

KEY BAORD



Key Name	SARADC
VOL+/RECOVERY	10
VOL-	170

Part D



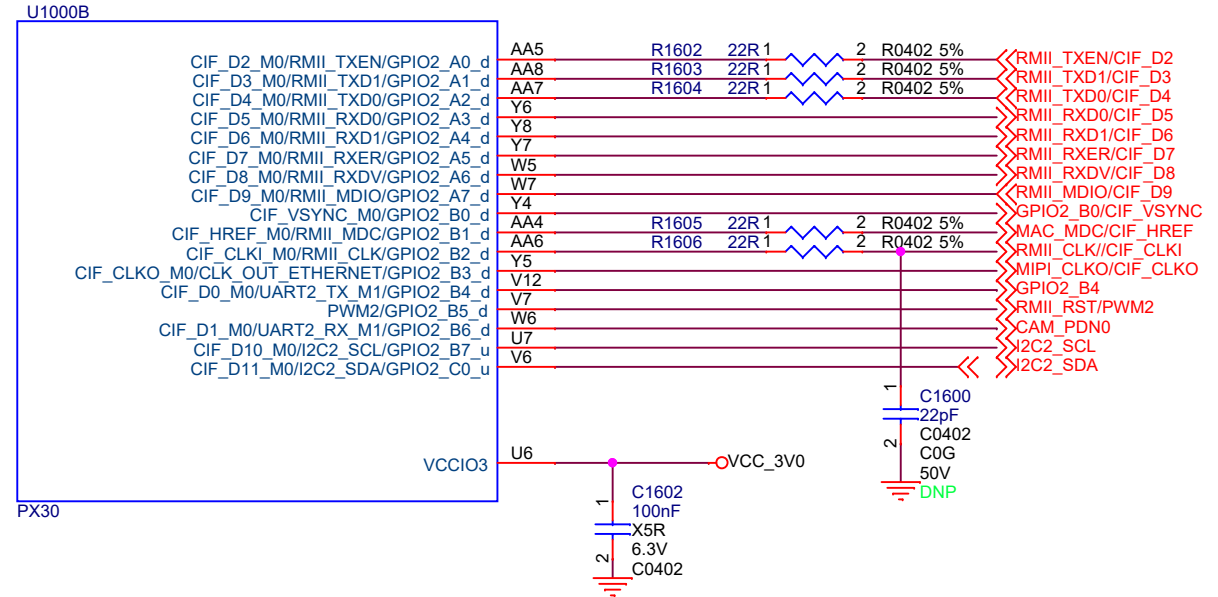
Note: All the Power filter capacitors should be placed close to the power pins of PX30

MIPI CSI

MIPI design rules:

1. Max intra-pair skew < 4ps;
2. Max length skew between clk and data < 7ps;
3. Max trace length < 7.2inches;
4. Max allowed via < 4;
5. Trace impedance 100ohm+/-10%;
6. The distance between other signals follows the 3W rule;

Part B



Note: All the Power filter capacitors should be placed close to the power pins of PX30

CIF/RMII

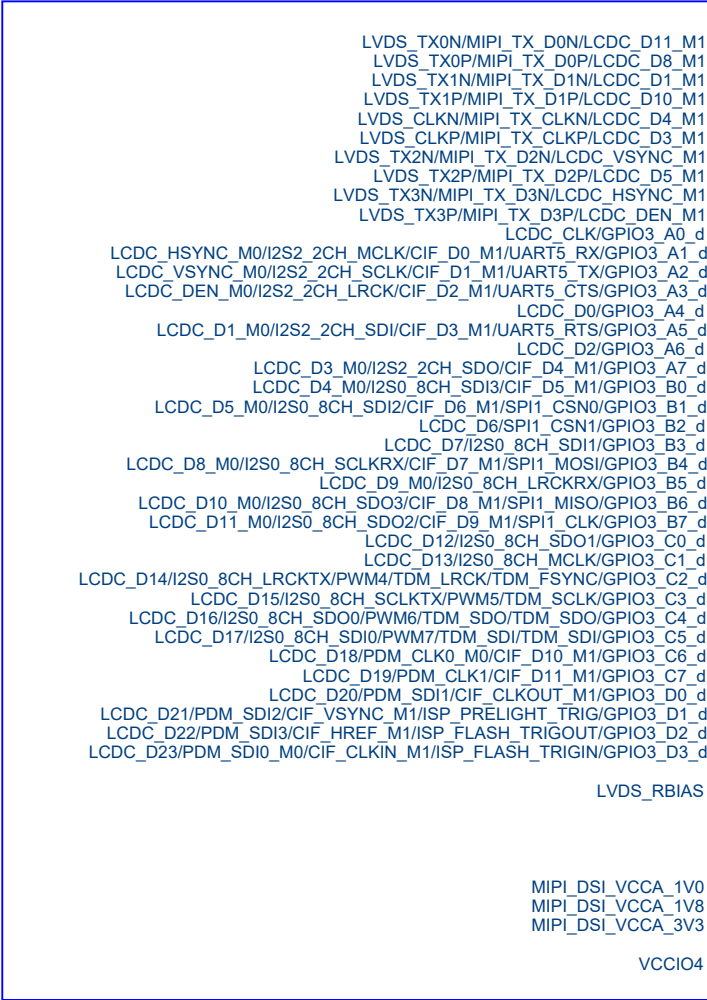
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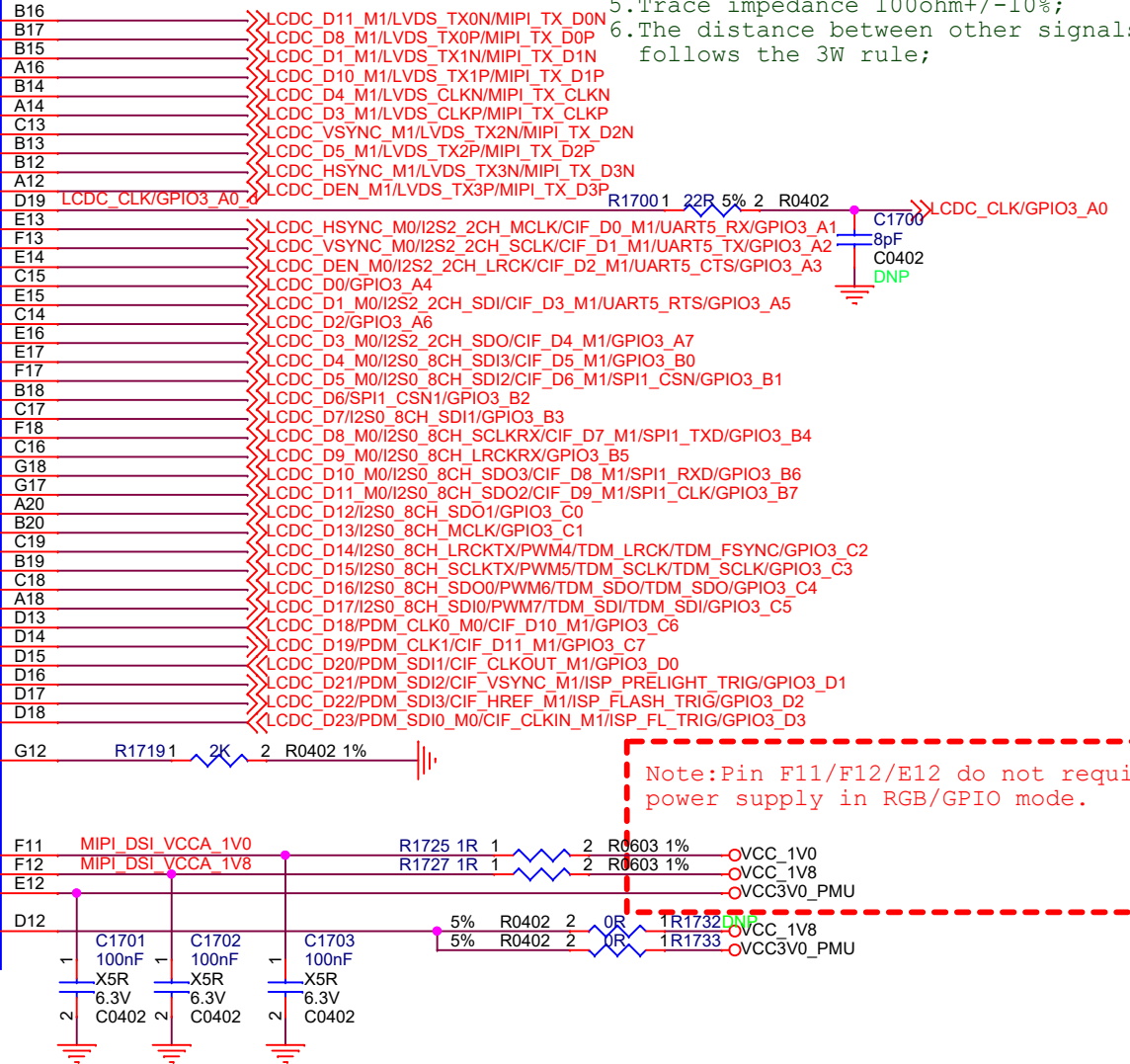
Project:	PX30 MINI EVB		
File:	16.PX30 DVP Interface		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	13 of 32

Part M

U1000M



PX30

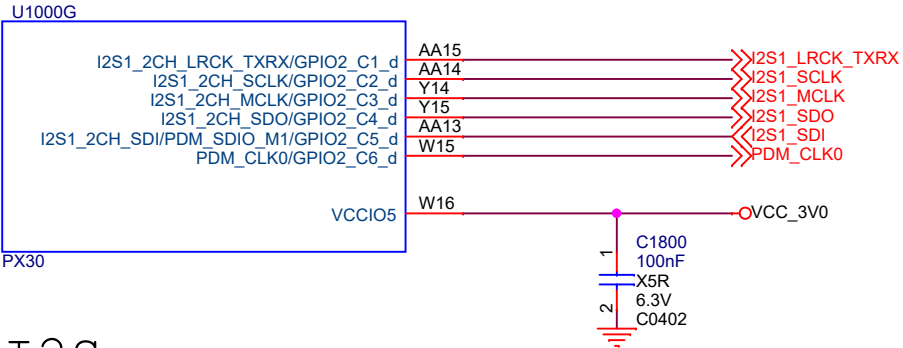


MIPI design rules:

1. Max intra-pair skew < 4ps;
2. Max length skew between clk and data < 7ps;
3. Max trace length < 7.2inchs;
4. Max allowed via < 4;
5. Trace impedance 100ohm+/-10%;
6. The distance between other signals follows the 3W rule;

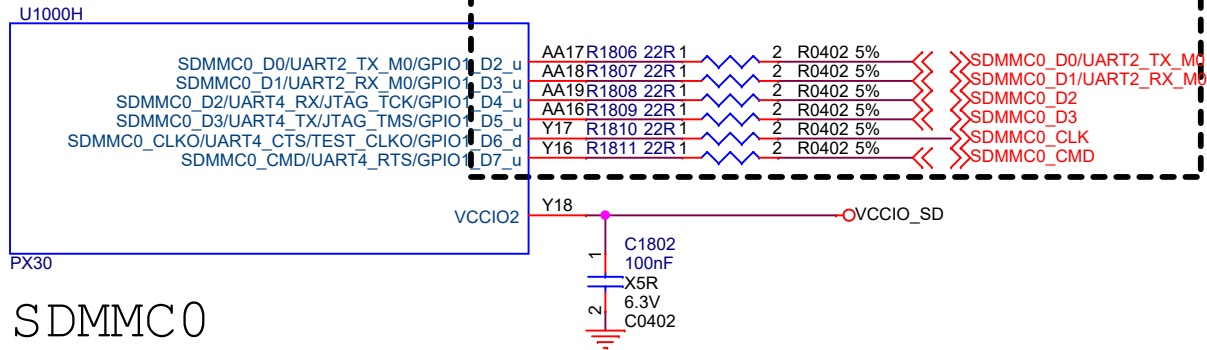
Project:	PX30 MINI EVB		
File:	17.PX30 MIPI DSI/LCDC		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	14 of 32

Part G



I2S

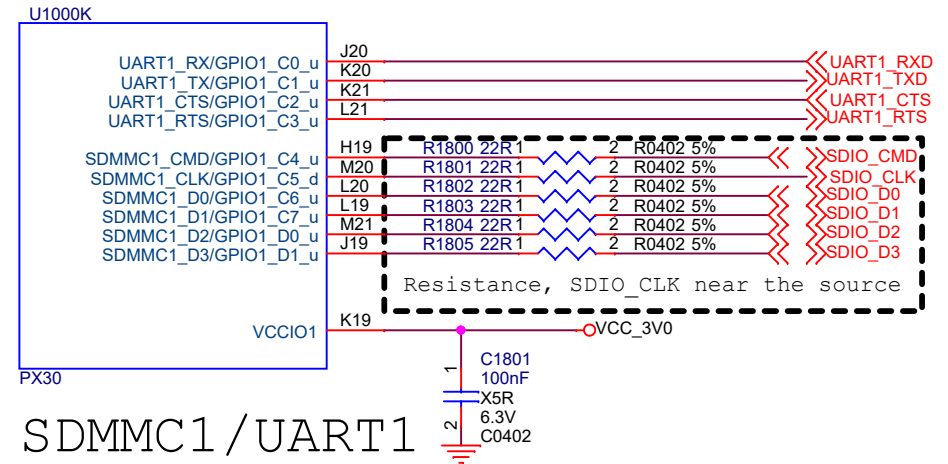
Part H



SDMMC0


Note:All the Power filter capacitors should be placed close to the power pins of PX30

Part K

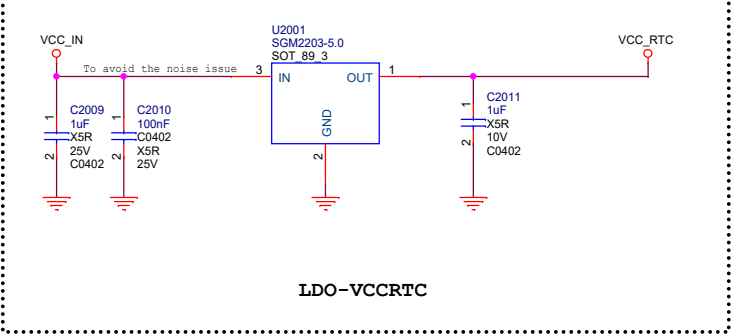
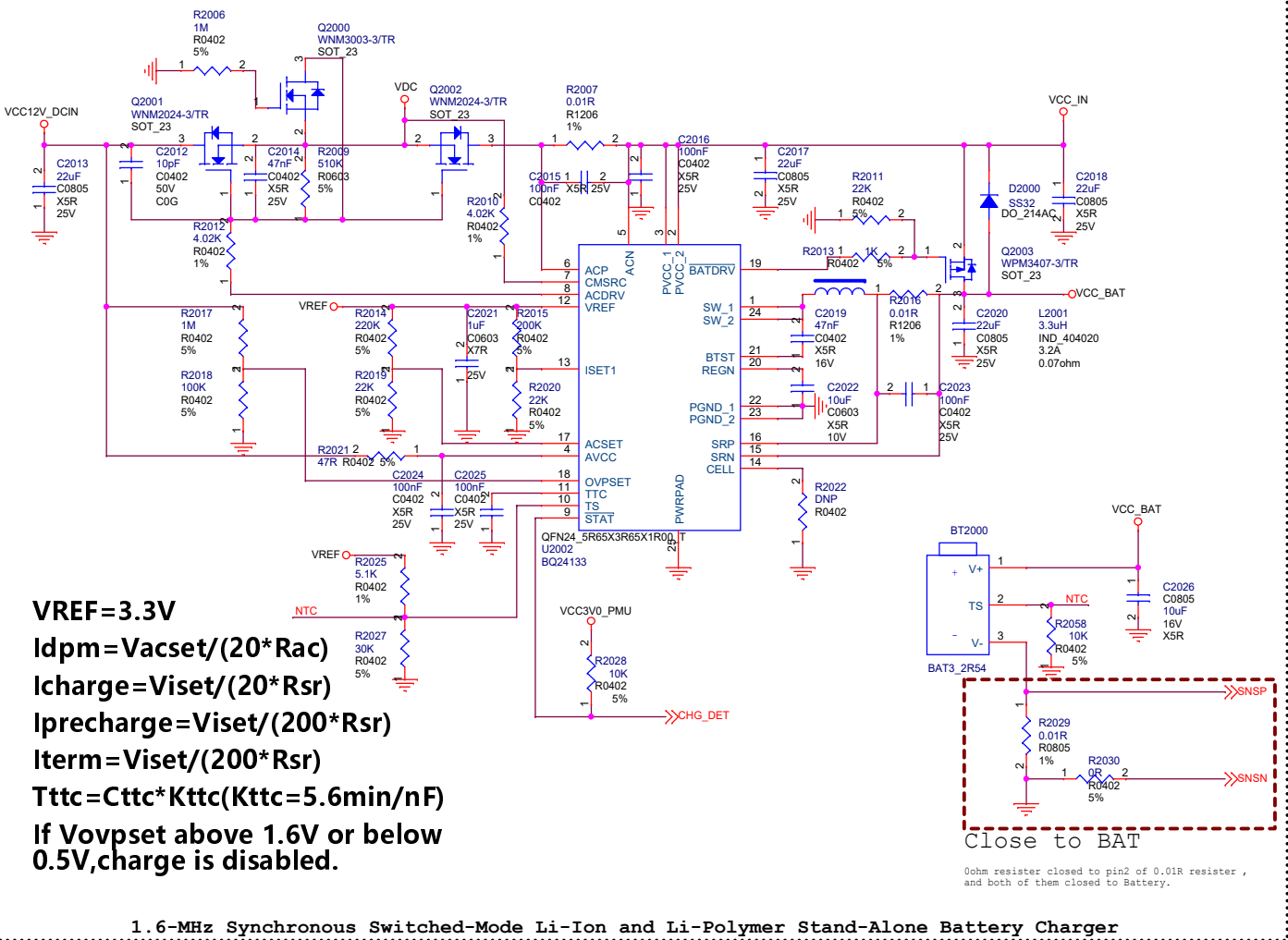
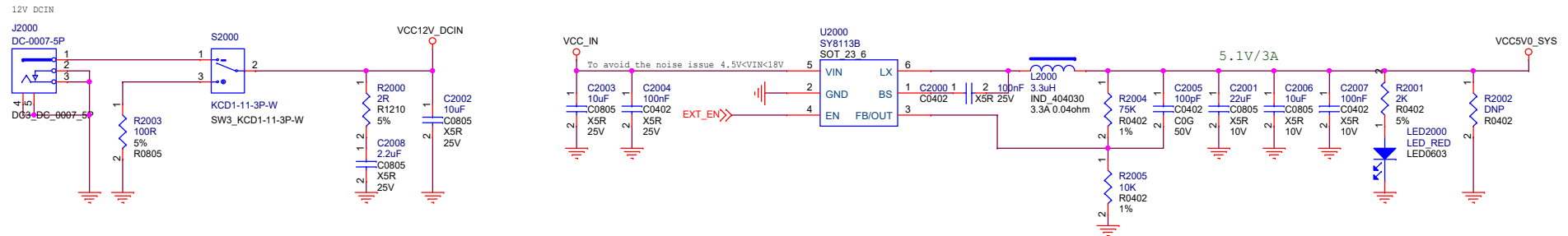


SDMMC1 / UART1

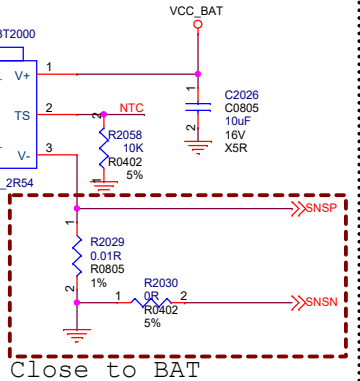
Note:All the Power filter capacitors should be placed close to the power pins of PX30

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Project:	PX30 MINI EVB		
File:	18.PX30 I2S/SDMMC0/SDMMC1		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	15 of 32

DC IN&SYSTEM Power



VREF=3.3V
 $I_{dpm} = V_{acset} / (20 * R_{ac})$
 $I_{charge} = V_{iset} / (20 * R_{sr})$
 $I_{precharge} = V_{iset} / (200 * R_{sr})$
 $I_{term} = V_{iset} / (200 * R_{sr})$
 $T_{ttc} = C_{ttc} * K_{ttc} (K_{ttc} = 5.6 \text{min/nF})$
 If V_{ovpset} above 1.6V or below 0.5V, charge is disabled.

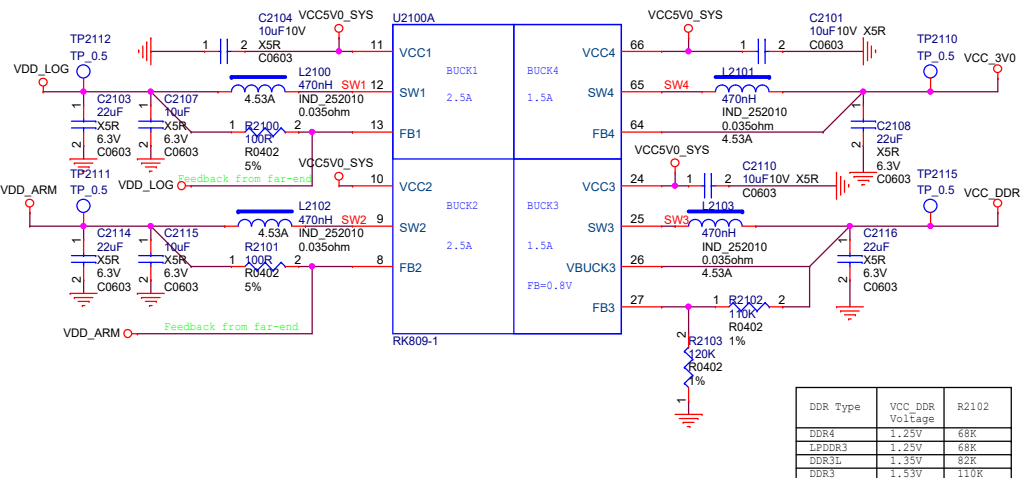


0ohm resistor closed to pin2 of 0.01R resistor , and both of them closed to Battery.

1.6-MHz Synchronous Switched-Mode Li-Ion and Li-Polymer Stand-Alone Battery Charger

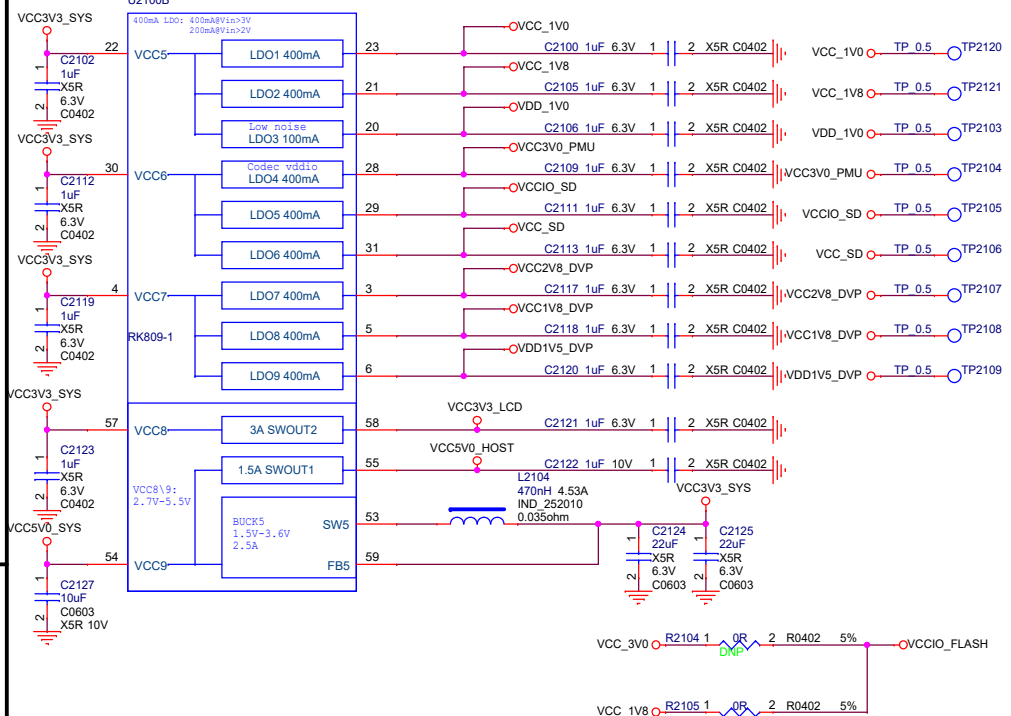
Rockchip 瑞芯微电子		Fuzhou Rockchip Electronics	
Project: PX30 MINI EVB			
File: 20.Power-DC IN			
Date: Monday, May 28, 2018		Rev: V1.0	
Designed by: XIACHF		Sheet: 16	of 32

PMIC RK809-1 DCDC

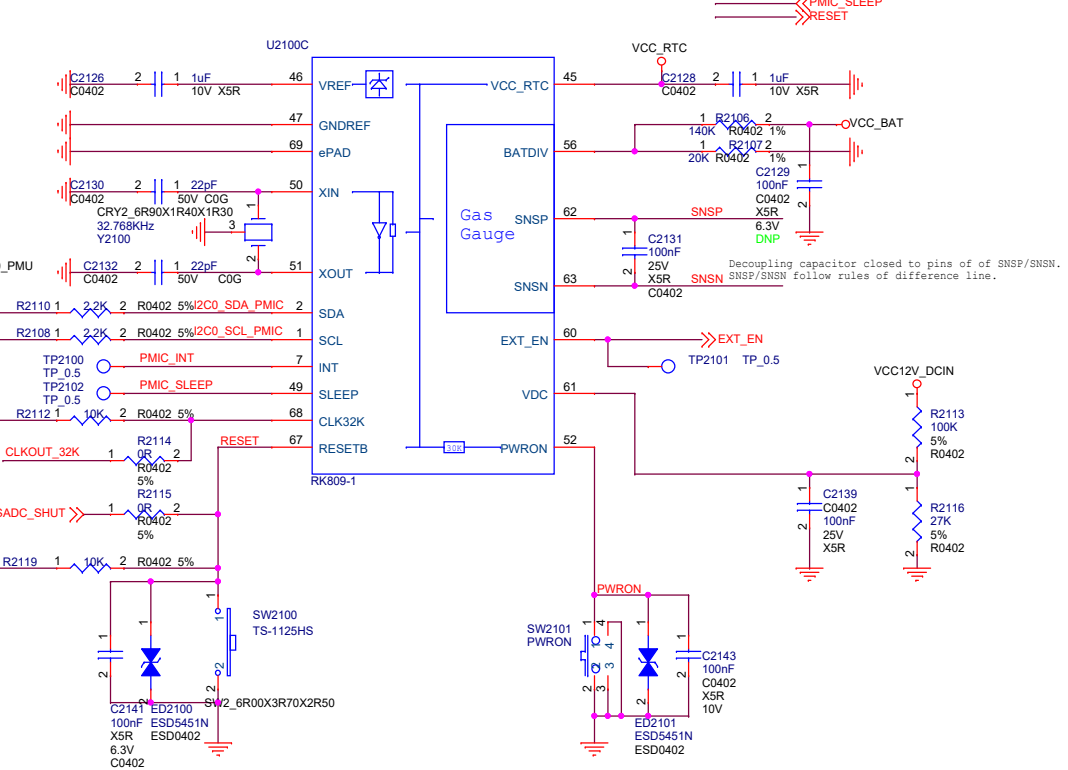


DDR Type	VCC_DDR Voltage	R2102
DDR4	1.25V	68K
LPDDR3	1.25V	68K
DDR3L	1.35V	82K
DDR3	1.35V	110K

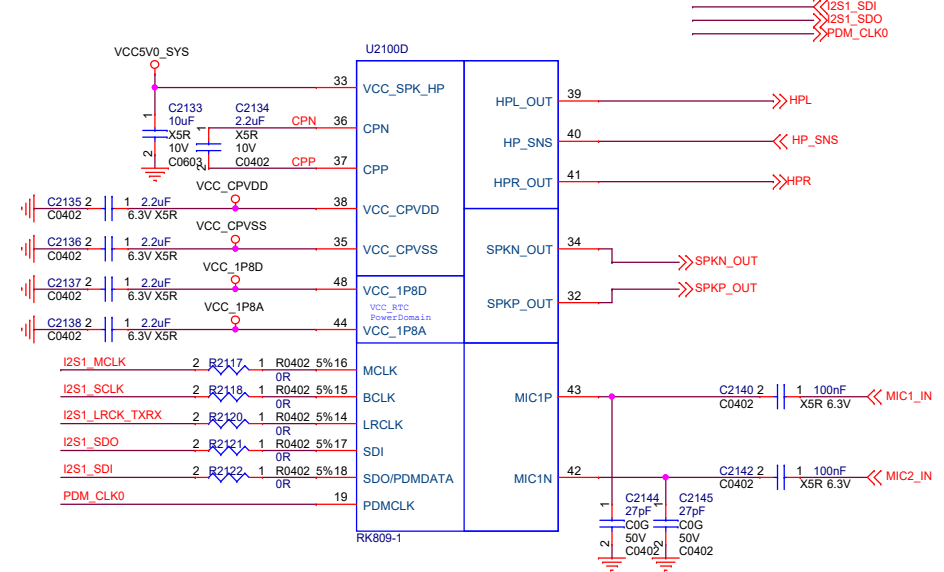
PMIC RK809-1 LDO



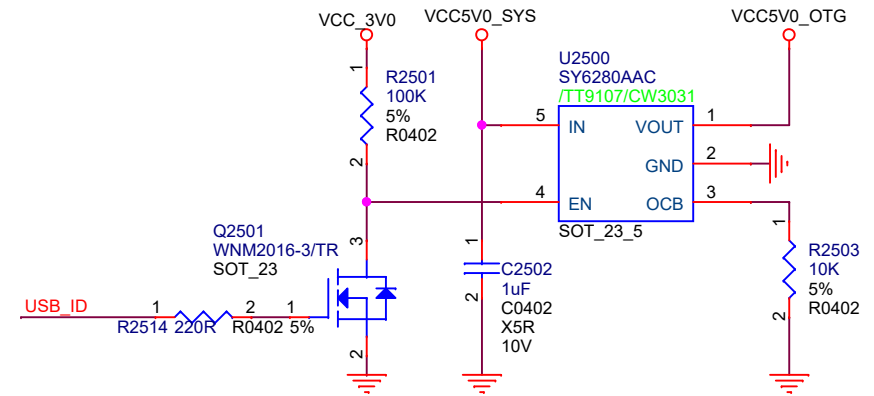
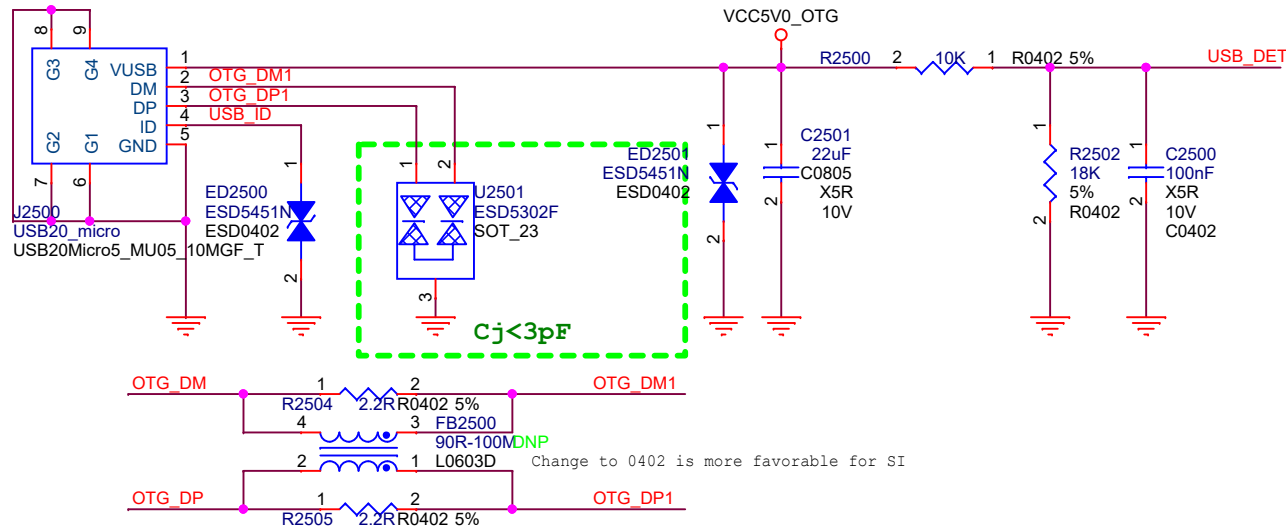
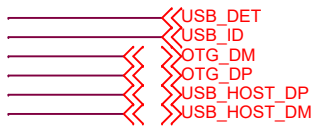
PMIC RK809-1 Management



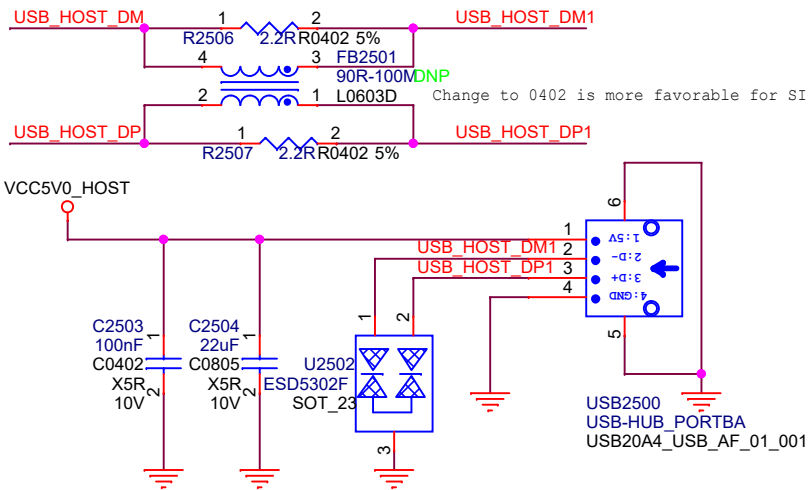
PMIC RK809-1 CODEC



USB OTG



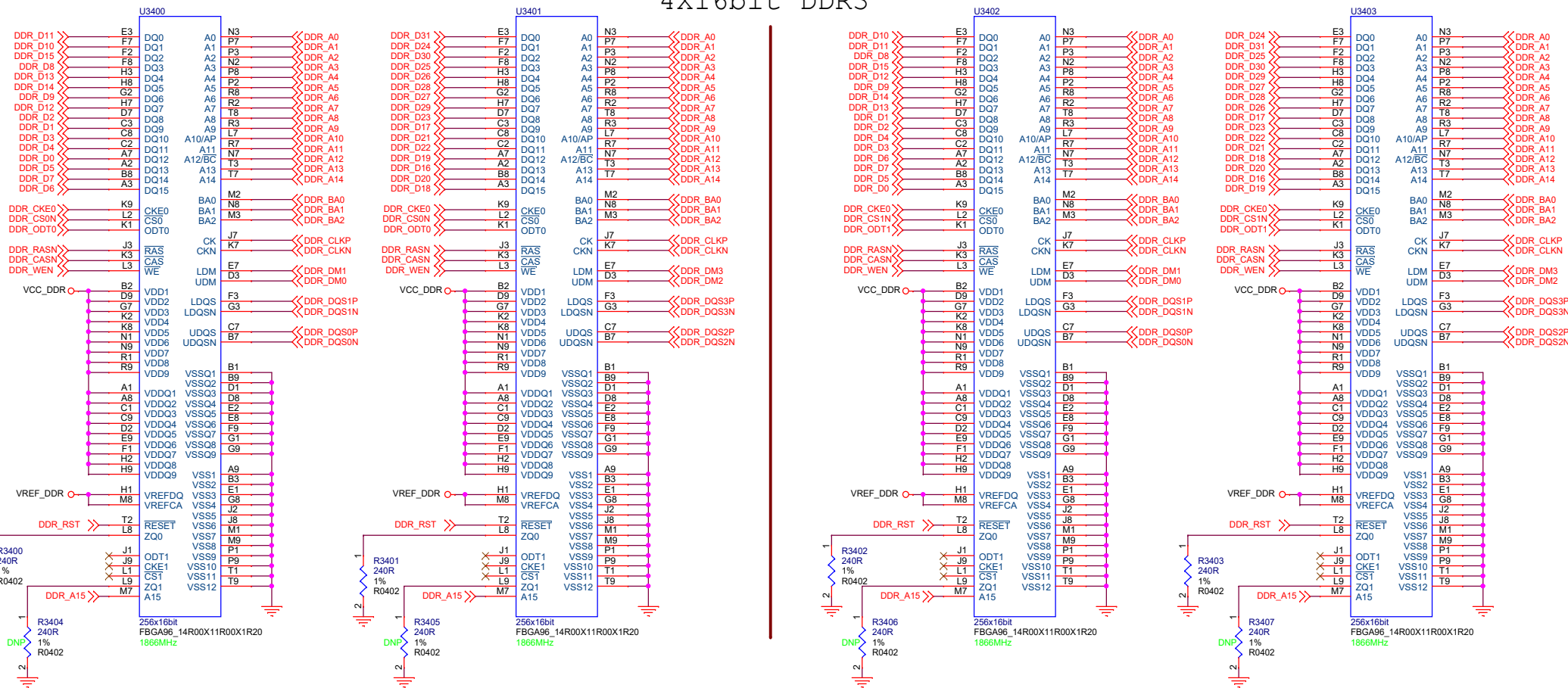
USB HOST



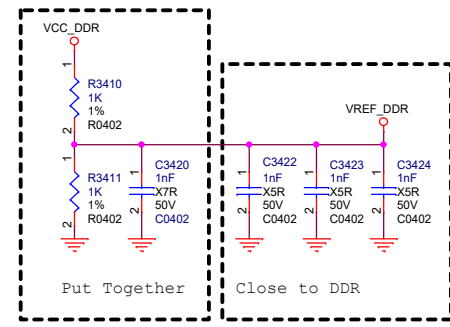
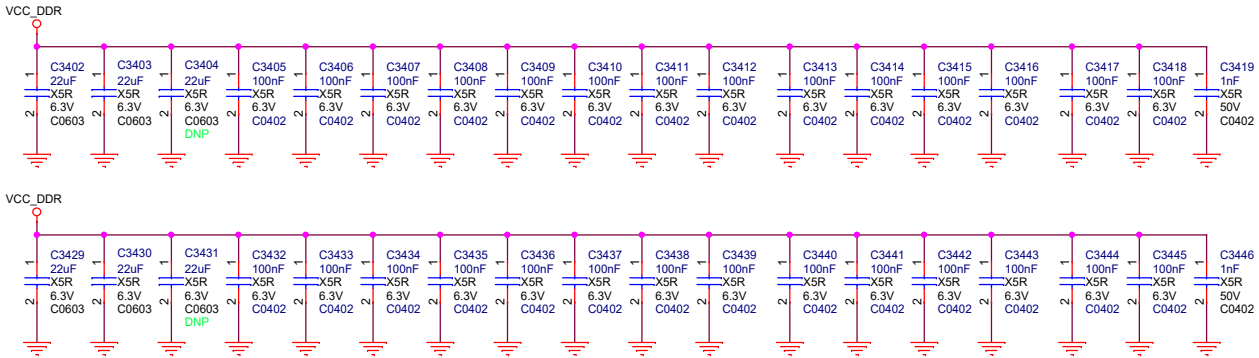
Fuzhou Rockchip Electronics 瑞芯微电子		
		Project: PX30 MINI EVB
File: 25.USB OTG/HOST	Date: Monday, May 28, 2018	Rev: V1.0
Designed by: XIAOHF	Sheet: 18 of 32	

Note: The simulation frequency of the template is 533MHz.

4X16bit DDR3



DDR3 FILTER

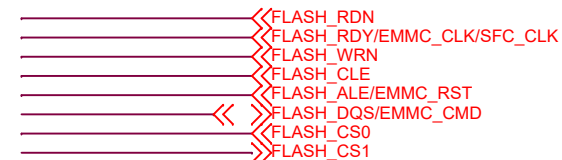


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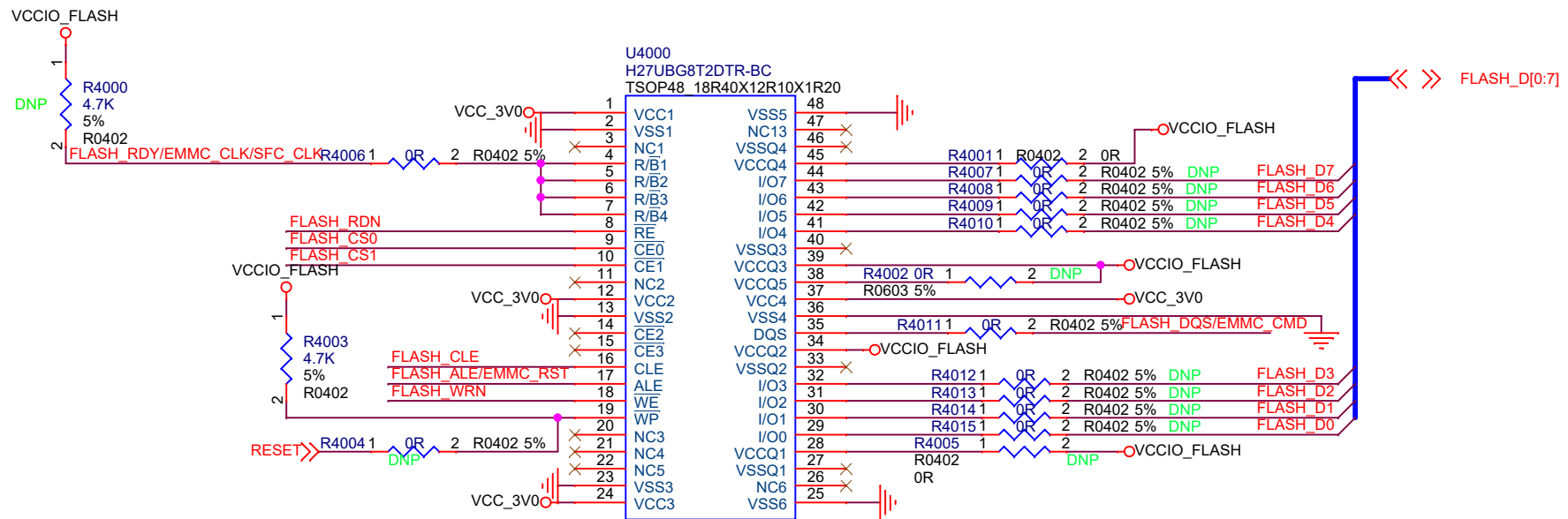
Project:	PX30 MINI EVB
File:	RAM DDR3 4x16bit
Date:	Monday, May 28, 2018
Designed by:	XIAOHF
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Nand Flash

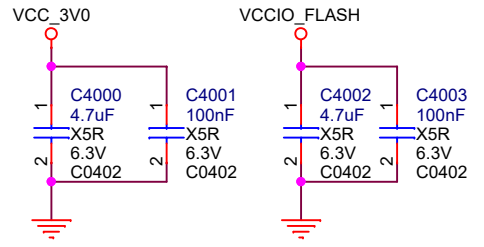
Remind: Refer to the latest AVL for parts selection.




Note: Flash_RDY pull-up resistor must be deleted in eMMC Flash mode and be mounted in Nand Flash mode.



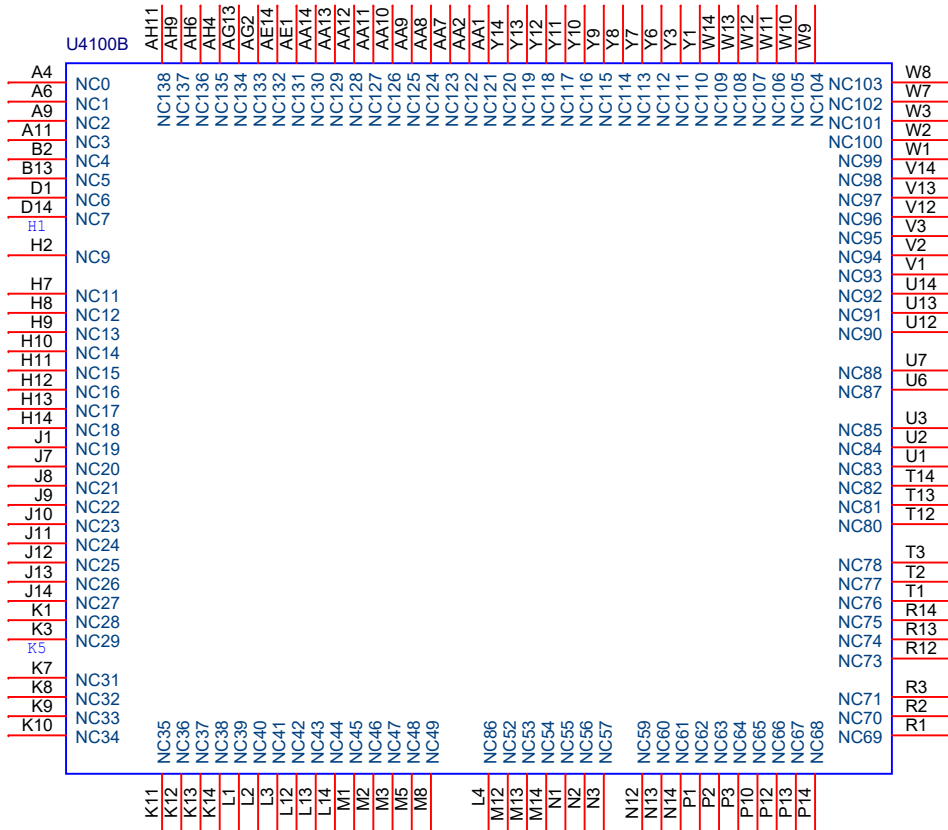
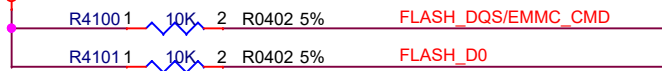
Note: if use toshiba and sandisk DDR mode, VCCQ1 and VCCQ4 must be connected to VCC_IO.



 瑞芯微电子		Fuzhou Rockchip Electronics	
Project:	PX30 MINI EVB		
File:	40.Flash-Nand Flash(option)		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	20 of 32

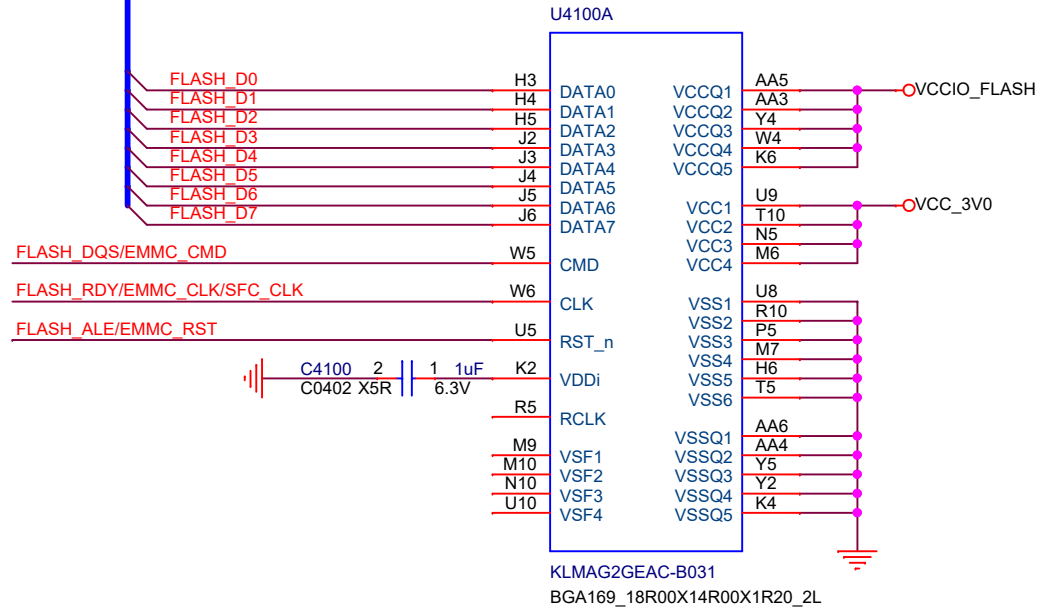
eMMC

VCCIO_FLASH

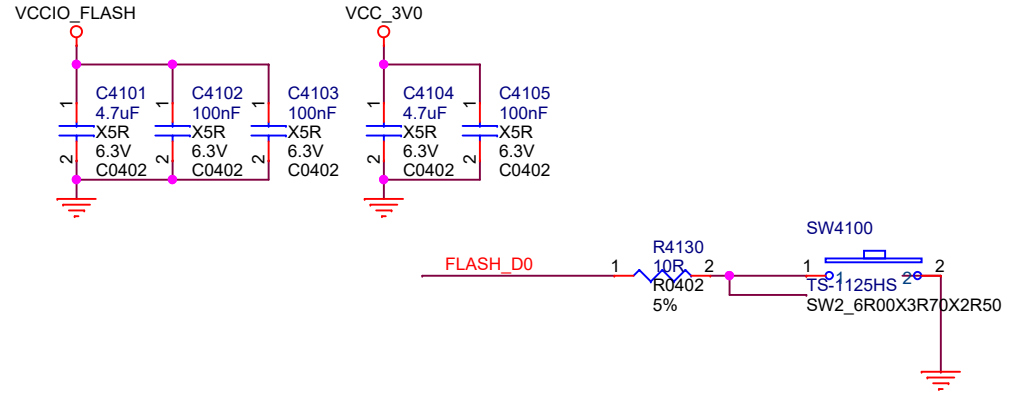


BGA169_18R00X14R00X1R20_2L
KLMAG2GEAC-B031

FLASH_D[0:7] << >>



KLMAG2GEAC-B031
BGA169_18R00X14R00X1R20_2L

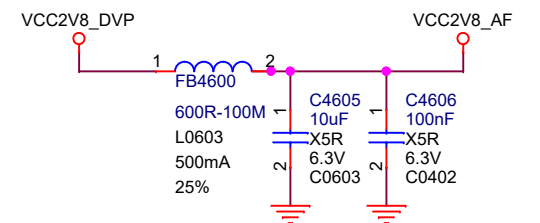
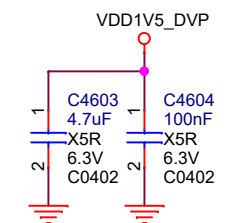
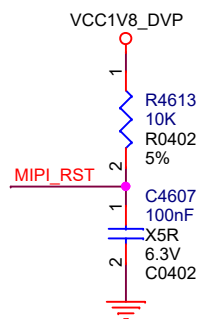
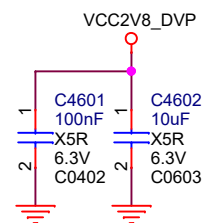
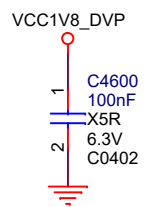
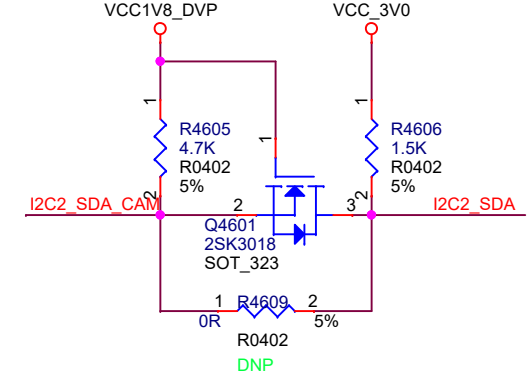
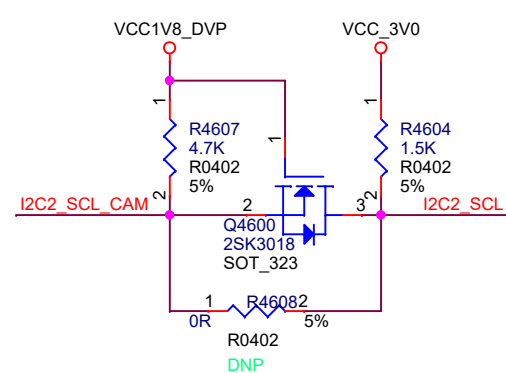
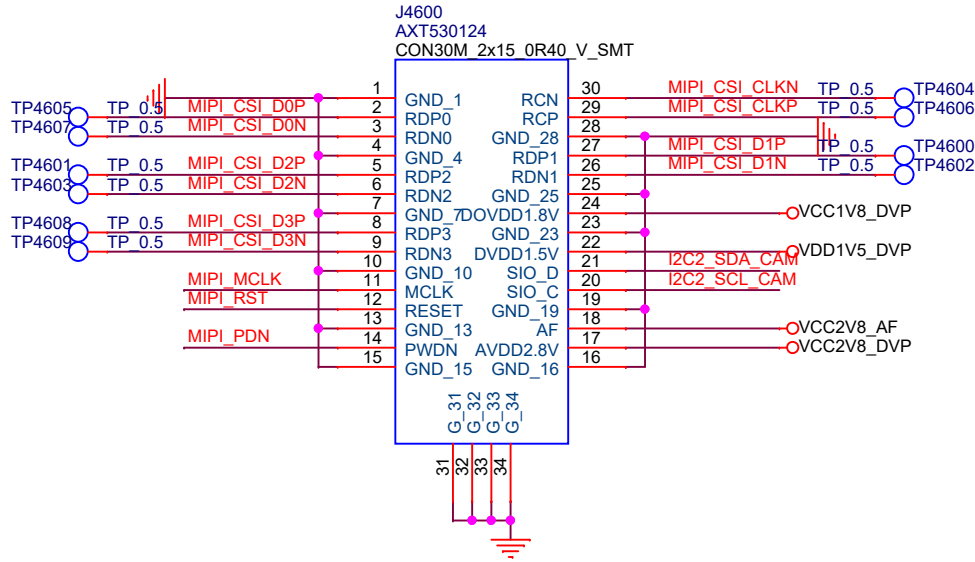
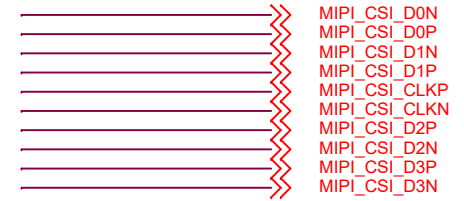
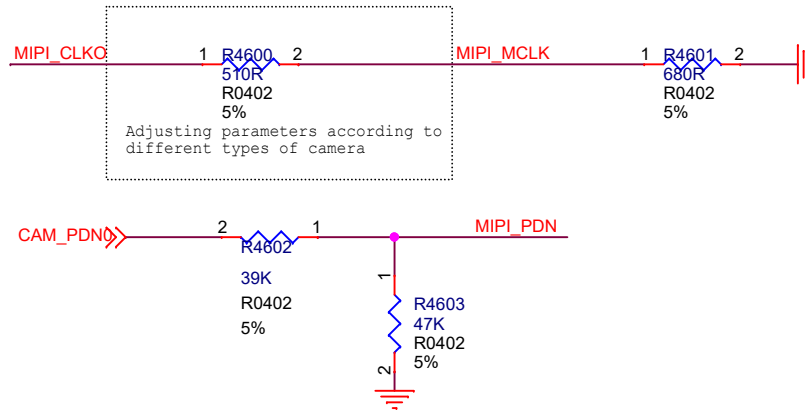


Note:
Short two TP points to Enter Maskrom Mode.

Remind: Refer to the latest AVL for parts selection.

Rockchip 瑞芯微电子		Fuzhou Rockchip Electronics	
Project:	PX30 MINI EVB		
File:	41.Flash-EMMC		
Date:	Friday, April 12, 2019	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	21 of 32

MIPI Camera

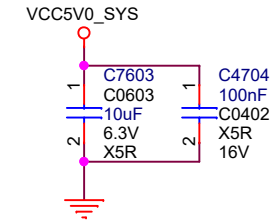
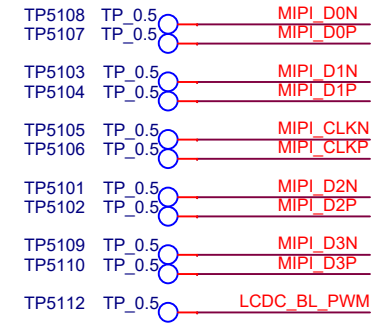
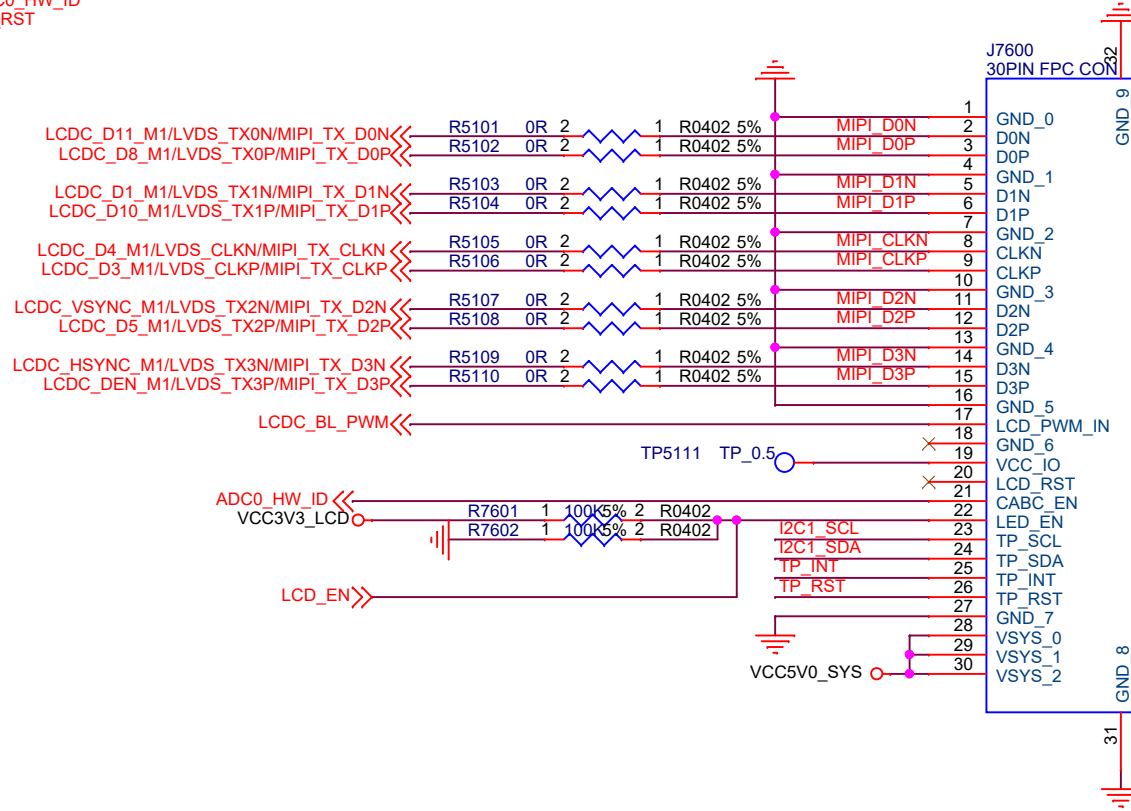


Rockchip 瑞芯微电子		Fuzhou Rockchip Electronics	
Project:	PX30 MINI EVB		
File:	46.Camera-MIPI CSI		
Date:	Friday, September 14, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	22 of 32

MIPI Panel

Note:

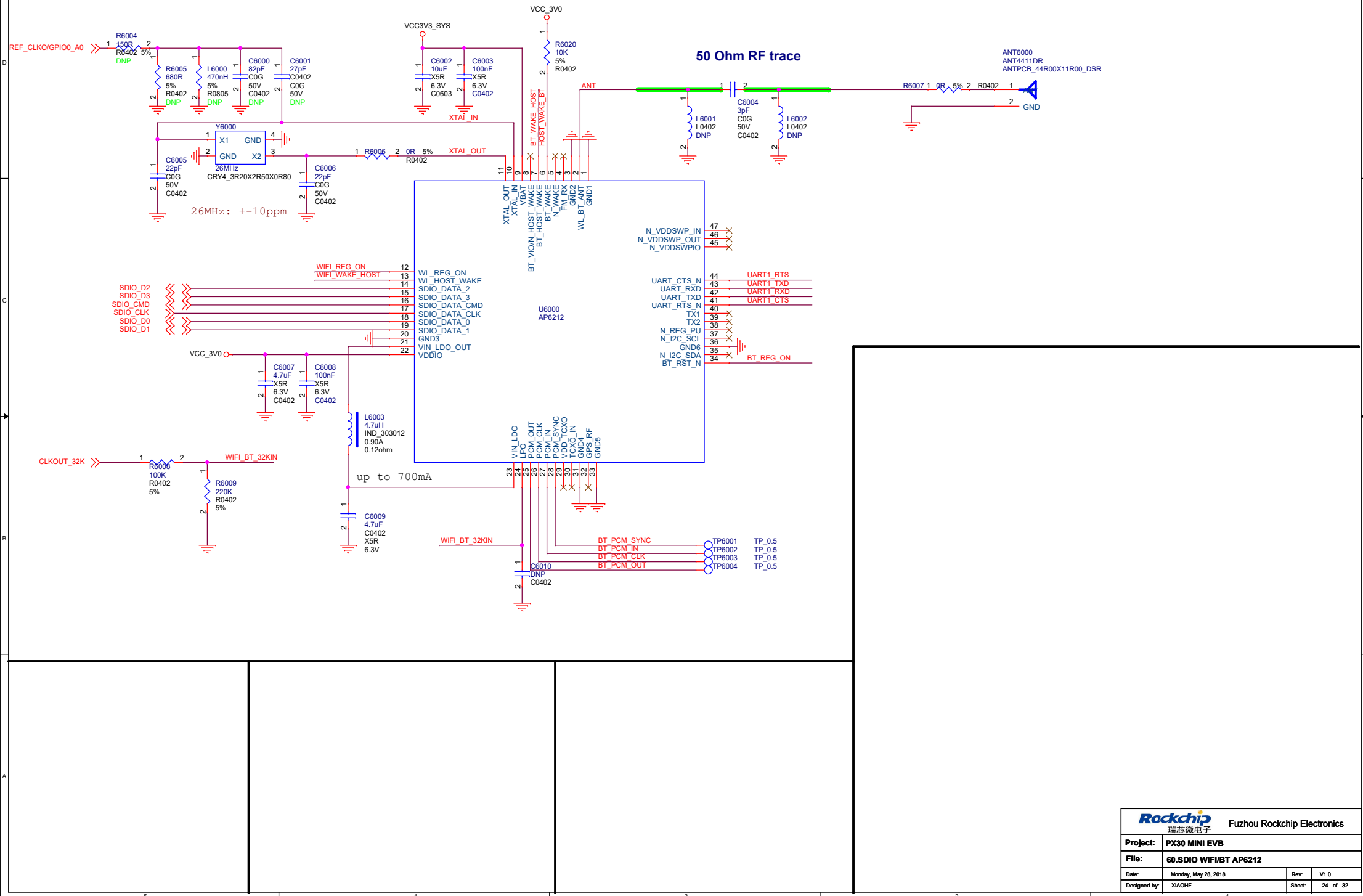
1. Use the MIPI output of RK618, please disconnect the PX30.
2. If need to support of LVDS/MIPI panel and HDMI with dual output same image, must use the physical cross screen panel, for example 1280x800, not 800x1280



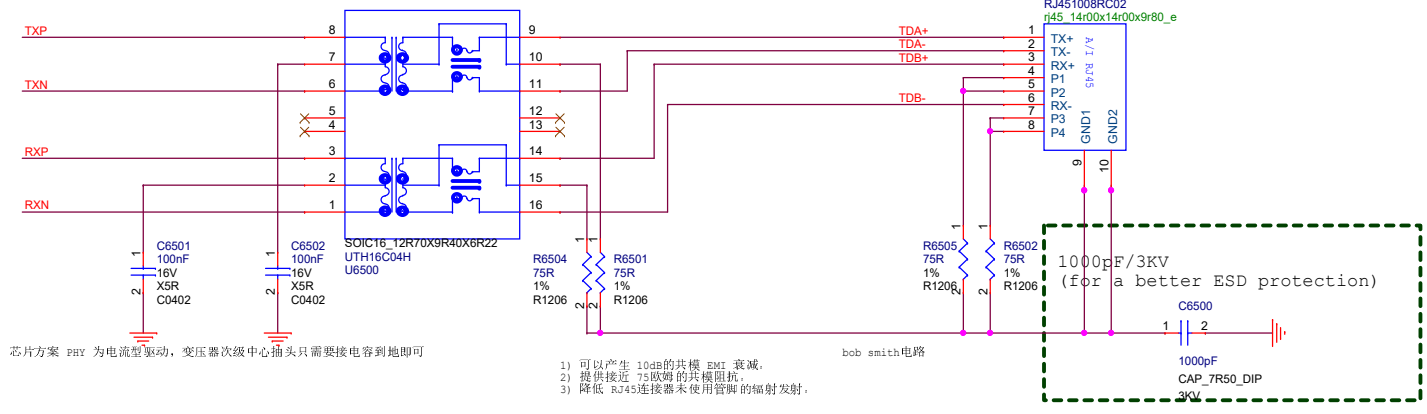
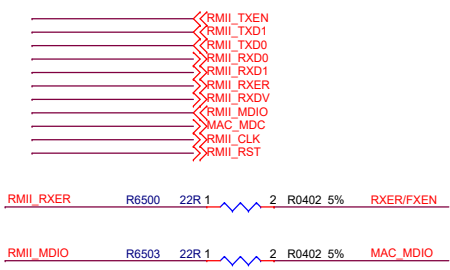
Rockchip
 瑞芯微电子 Fuzhou Rockchip Electronics

Project:	PX30 MINI EVB		
File:	52.LCM-MIPI Panel		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	23 of 32

WIFI/BT MODULE

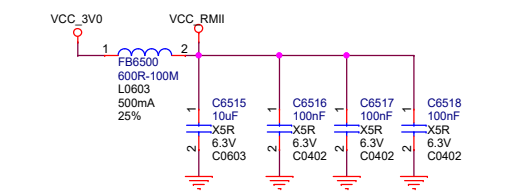
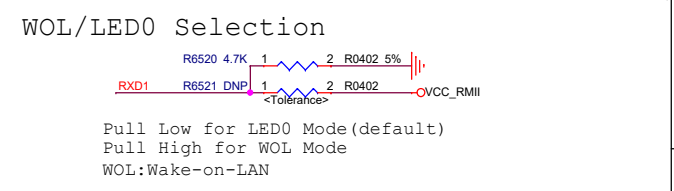
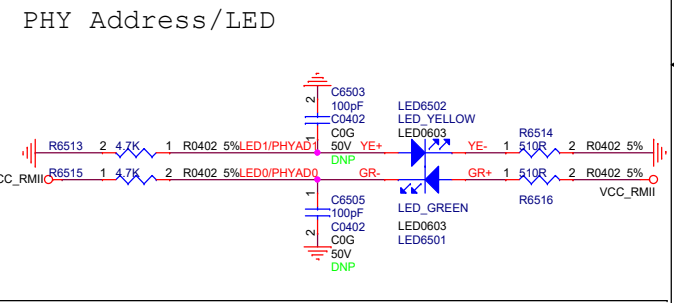
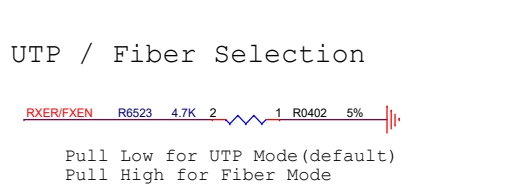
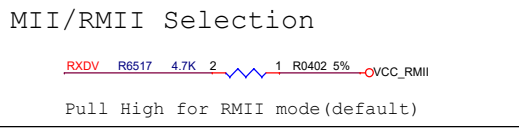
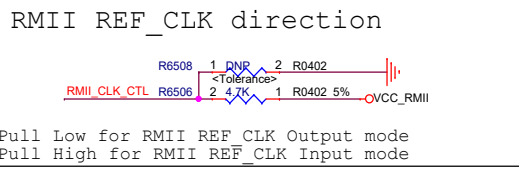
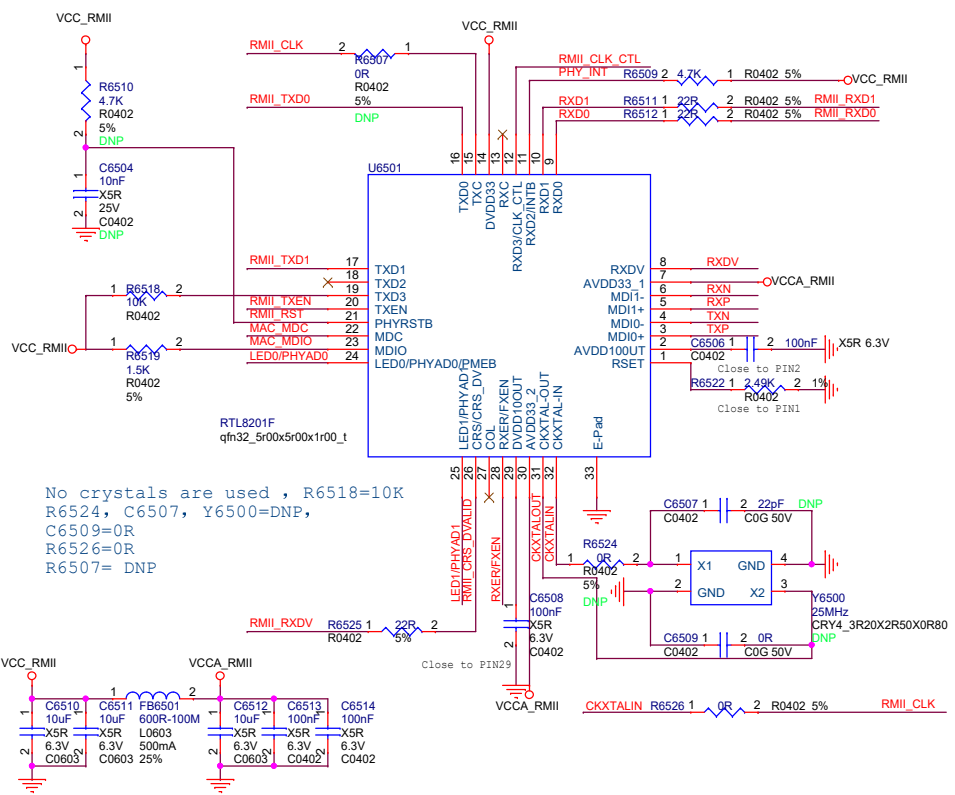


Project:	PX30 MINI EVB		
File:	60.SDIO WIFI/BT AP6212		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	24 of 32

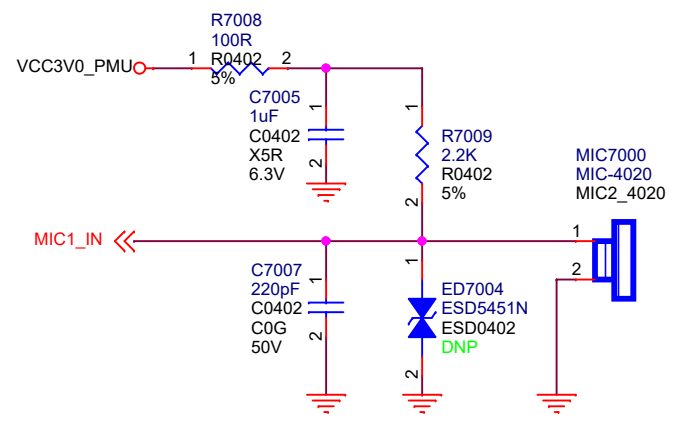
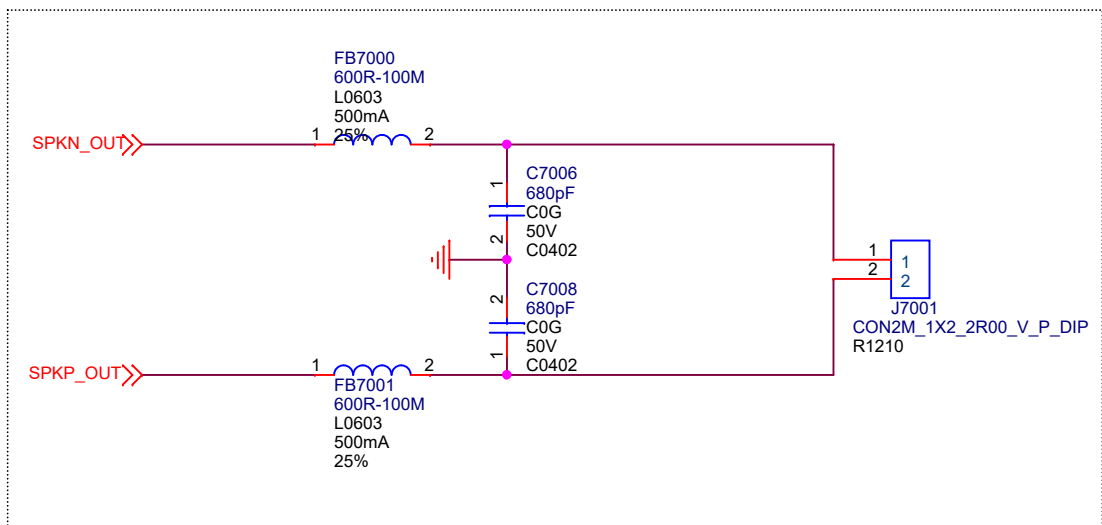
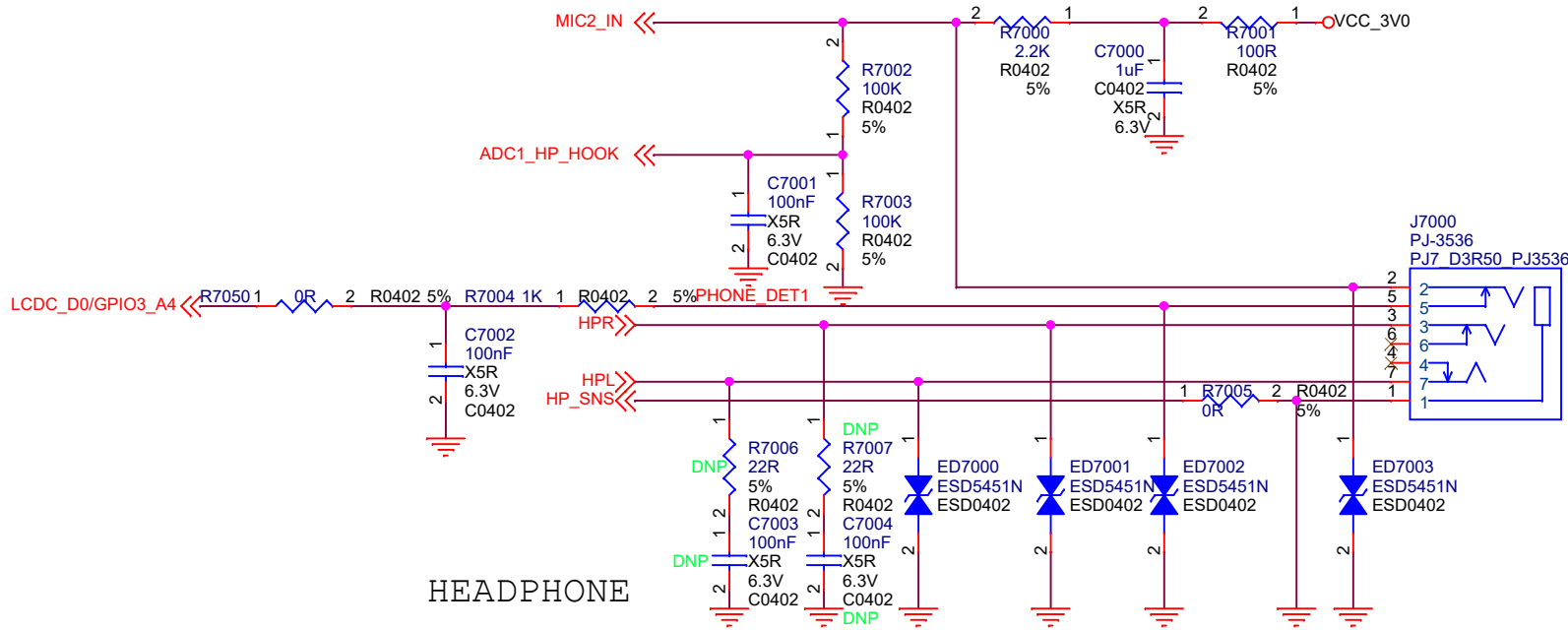


芯片方案 PHY 为电流型驱动，变压器次级中心抽头只需要接电容到地即可

- 1) 可以产生 10dB 的共模 EMI 衰减;
- 2) 提供接近 75 欧姆的共模阻抗;
- 3) 降低 RJ45 连接器未使用管脚的辐射发射;



Rockchip 瑞芯微电子			
Fuzhou Rockchip Electronics			
Project:	PX30 MINI EVB		
File:	65.RJ45-100M-RTL8201		
Date:	Tuesday, September 25, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	25 of 32

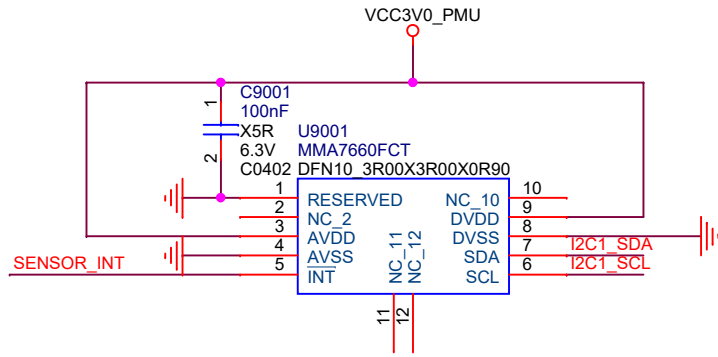


Rockchip 瑞芯微电子		Fuzhou Rockchip Electronics	
Project:	PX30 MINI EVB		
File:	70.AUDIO1		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	26 of 32

>>>I2C1_SDA
>>>I2C1_SCL

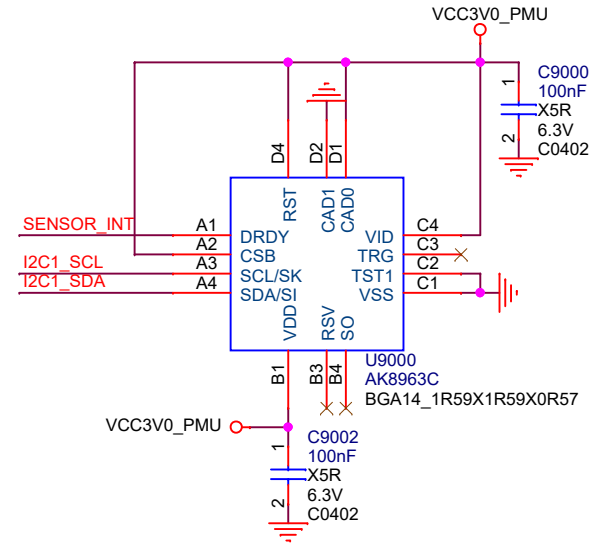
<<<SENSOR_INT

G-sensor



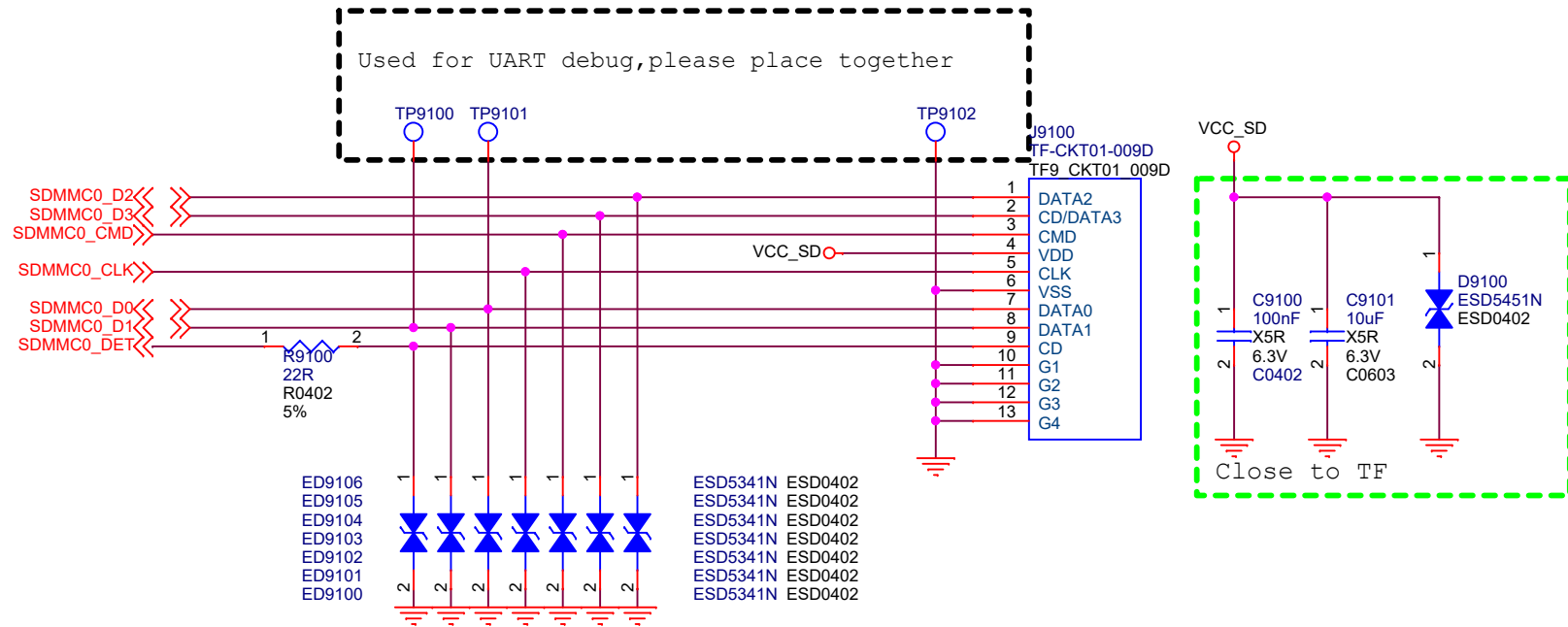
Compass


Note:
The first pin of AK8963C must be place on the lower left corner of PCB.

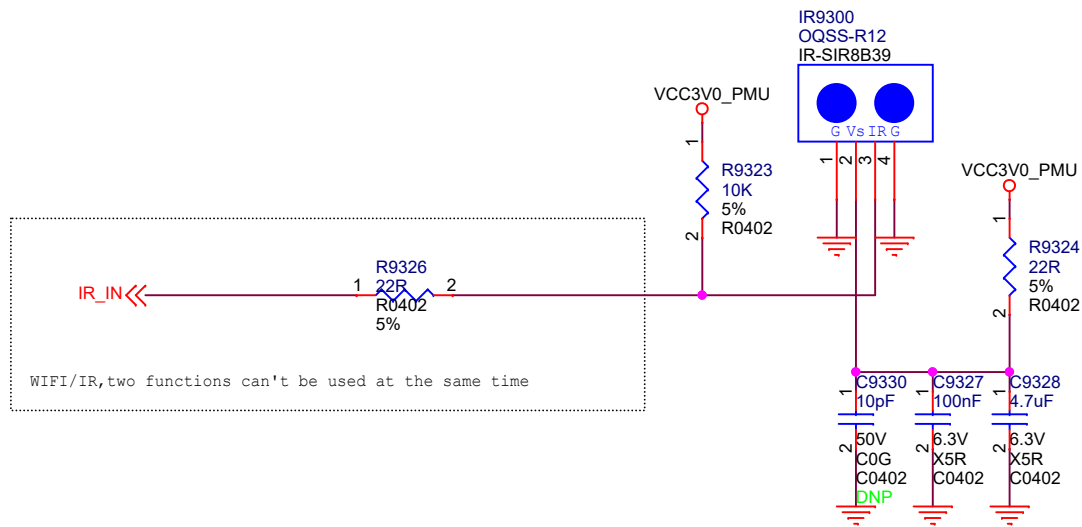


Project:	PX30 MINI EVB		
File:	90.Sensor		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	27 of 32

TF Card



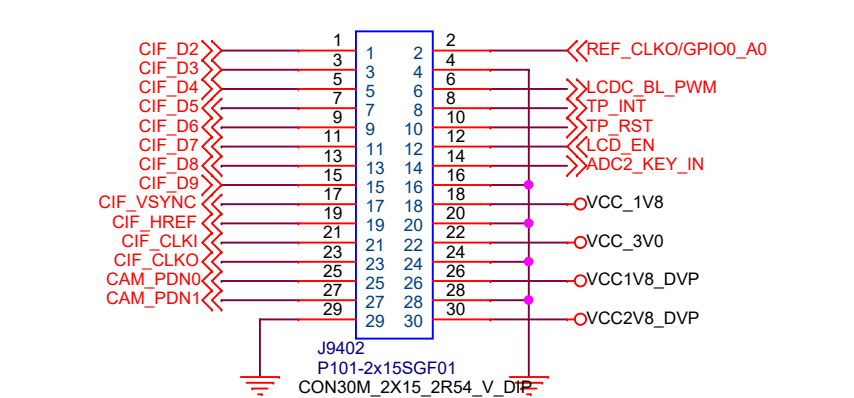
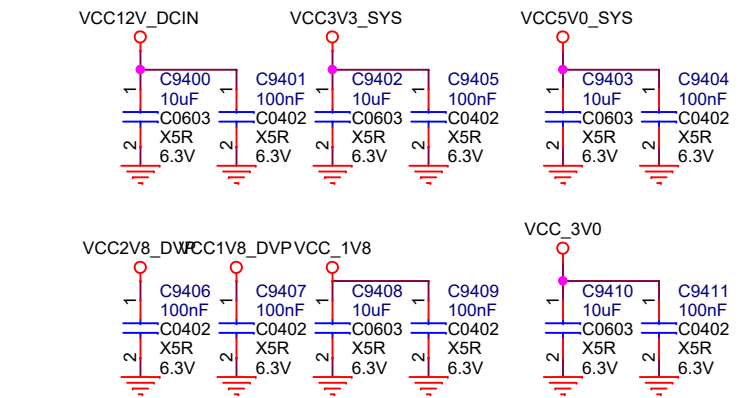
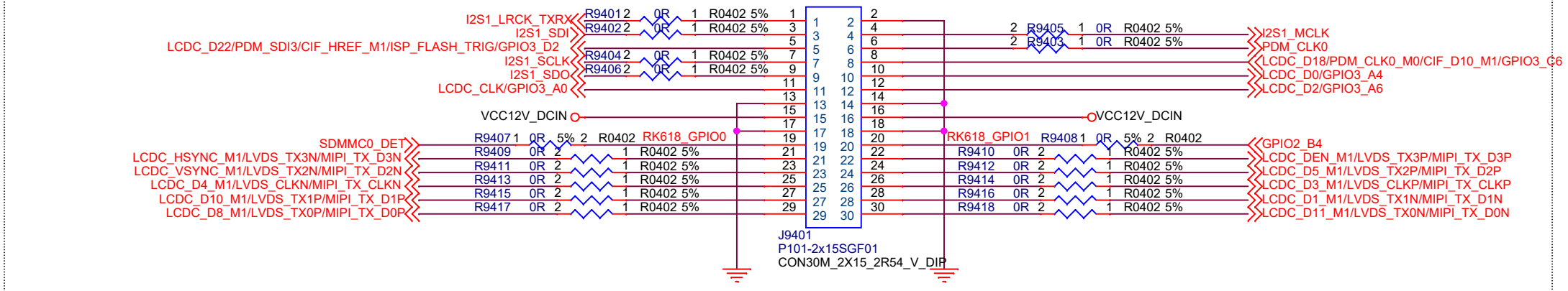
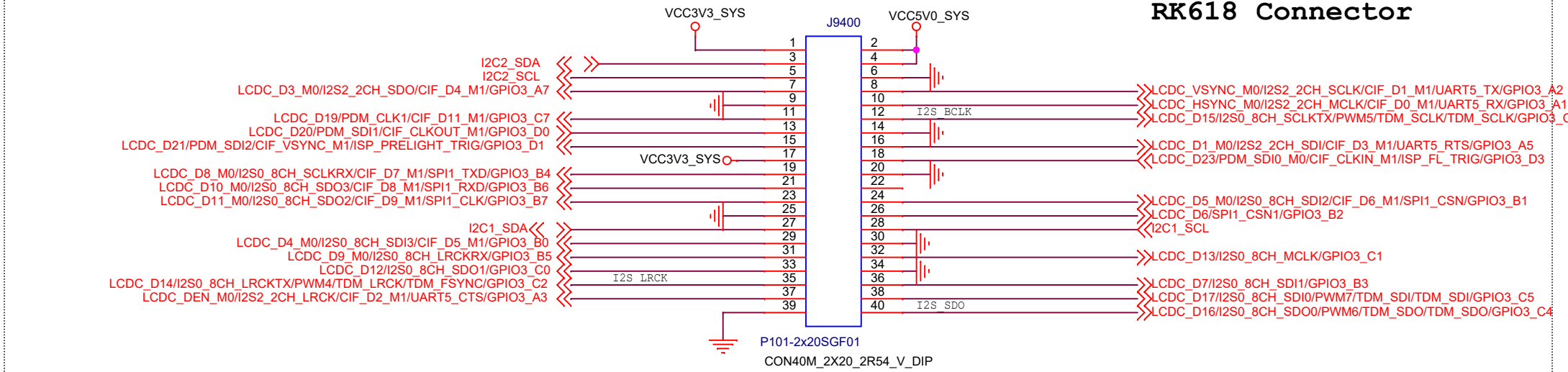
 Rockchip 瑞芯微电子		Fuzhou Rockchip Electronics	
Project:	PX30 MINI EVB		
File:	91.TF Card		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	28 of 32




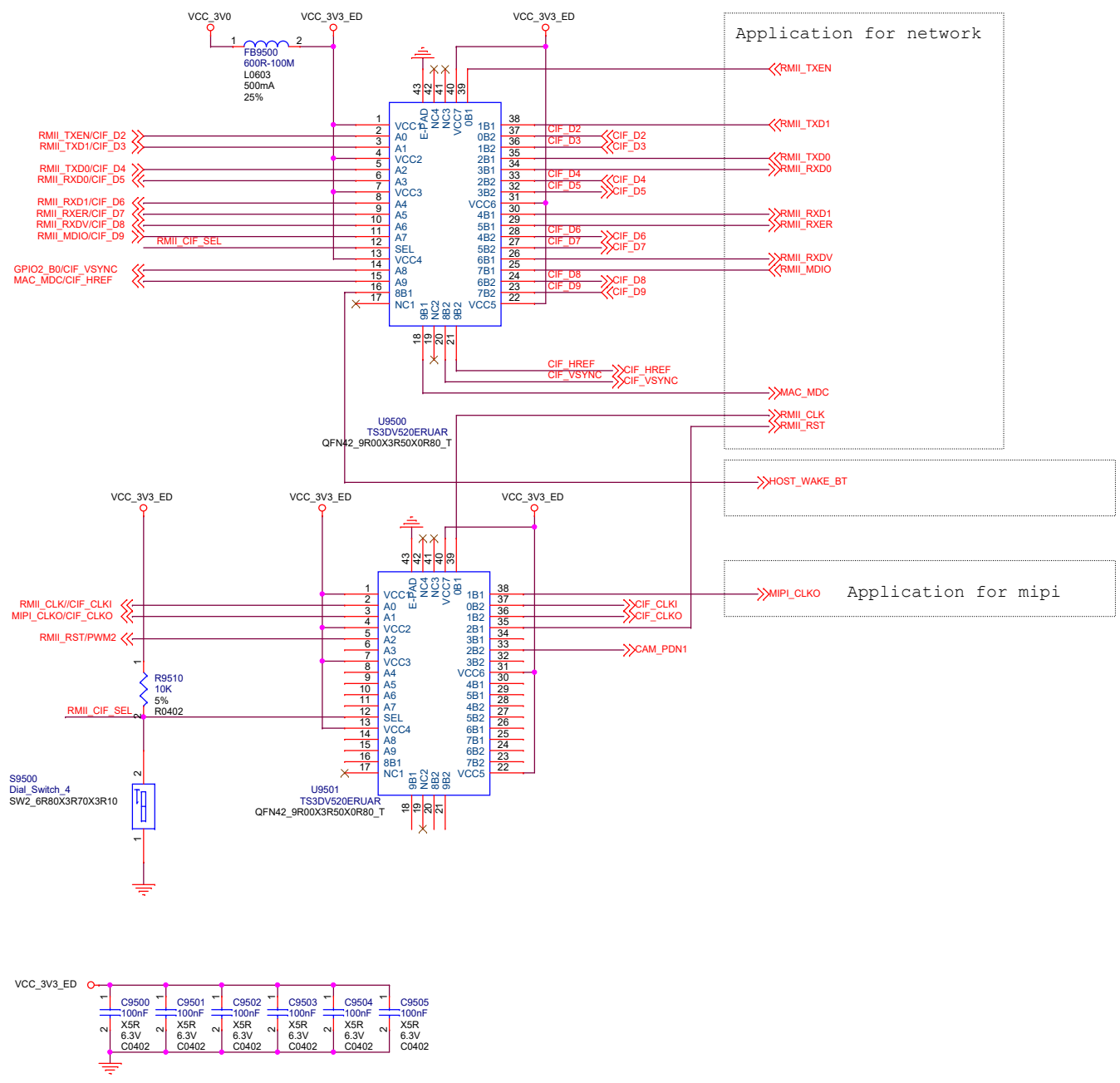
IR Receiver

Rockchip 瑞芯微电子		Fuzhou Rockchip Electronics	
Project:	PX30 MINI EVB		
File:	93.IR		
Date:	Monday, May 28, 2018	Rev:	V1.0
Designed by:	XIAOHF	Sheet:	29 of 32

RK618 Connector



 Fuzhou Rockchip Electronics 瑞芯微电子	
Project:	PX30 MINI EVB
File:	94.40PIN/30PIN Connect
Date:	Monday, May 28, 2018
Designed by:	XIAOHF
Rev:	V0.1
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Project:	PX30 MINI EVB		
File:	95.SWITCH		
Date:	Monday, May 28, 2018	Rev:	V0.1
Designed by:	XIAOHF	Sheet:	31 of 32



M9900
MARK



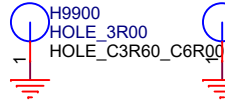
M9901
MARK



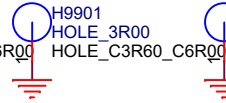
M9902
MARK



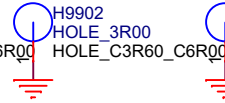
M9903
MARK



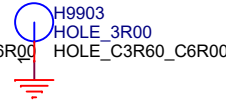
H9900
HOLE_3R00
HOLE_C3R60_C6R00



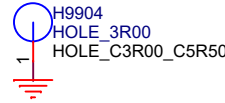
H9901
HOLE_3R00
HOLE_C3R60_C6R00



H9902
HOLE_3R00
HOLE_C3R60_C6R00



H9903
HOLE_3R00
HOLE_C3R60_C6R00



H9904
HOLE_3R00
HOLE_C3R00_C5R50

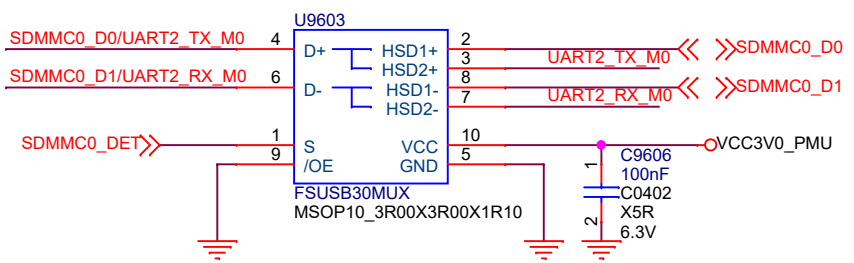
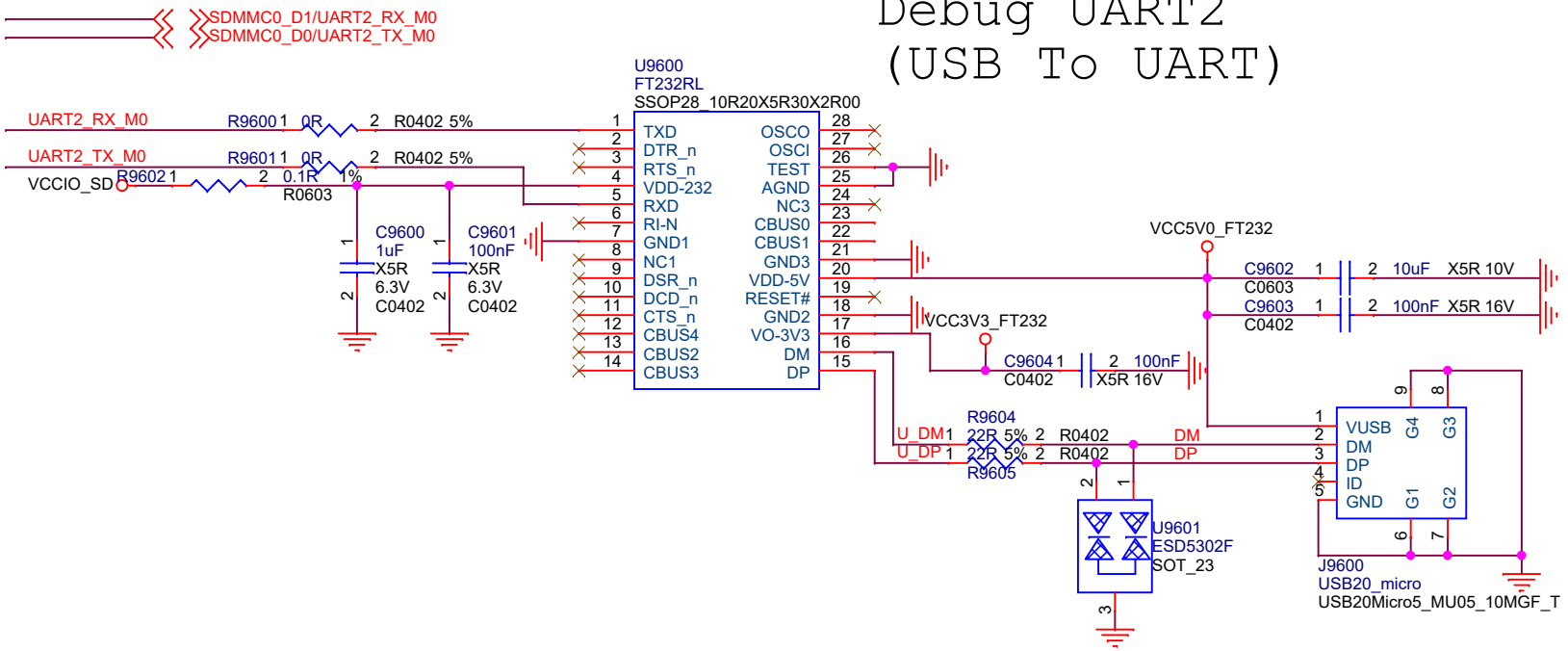


瑞芯微电子

Fuzhou Rockchip Electronics

Project:	PX30 MINI EVB		
File:	99.MARK/HOLE		
Date:	Monday, May 28, 2018	Rev:	V0.1
Designed by:	XIAOHF	Sheet:	32 of 32

Debug UART2 (USB To UART)



Truth Table

S	\overline{OE}	Function
X	H	Disconnect
L	L	D+, D- = HSD1 _n
H	L	D+, D- = HSD2 _n

Rockchip
瑞芯微电子 Fuzhou Rockchip Electronics

Project:	PX30 MINI EVB		
File:	96.UART Debug		
Date:	Monday, May 28, 2018	Rev:	V0.1
Designed by:	XIAOHF	Sheet:	32 of 35